32-Bit Proprietary Microcontroller

LSI Network Security System

MB91401

DESCRIPTION

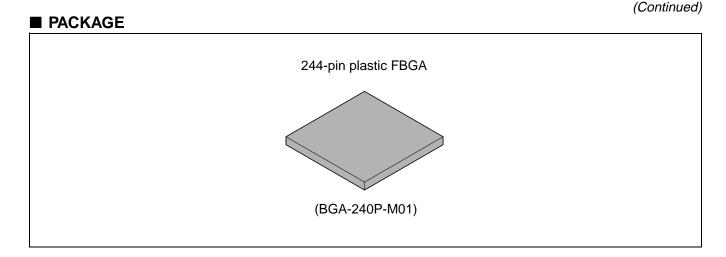
The MB91401 is a network security LSI incorporating a Fujitsu's 32-bit, FR-family RISC microcontroller with 10/ 100Base-T MAC Controller, encryption function and authentication function. The LSI contains an encryption authentication hardware accelerator that boosts the LSI's performance for encryption and authentication communication (IKE/IPsec/SSL) to be demanded further.

The MAC controller has a packet filtering function that reduces the load on the CPU for an increasing amount of packet processing. In addition, the board has the External interface for high-speed data communication with various external hosts, USB ports as general-purpose interfaces, and various card interfaces.

FEATURES

• Encryption and authentication processing by hardware accelerator function

The LSI performs processing five times faster than by the conventional combination of encryption/authentication hardware macros and software or about 400 times faster than by software only. In addition, CPU processing load factor to be involved in the encryption and the authentication processing can be decreased to 1/5 or less. Also, the LSI uses the embedded accelerator to execute that public-key encryption algorithm about 100 times faster than by software processing, which generally puts an extremely heavy load microcontrollers.





- For DES-ECB/DES-CBC/3DES-ECB/3DES-CBC mode*
- For MD5/SHA-1/HMAC-MD5/HMAC-SHA-1 mode
- DH group: for 1 (MODP 768 bit) /2 (1024 bit)

For the encryption/authentication macros, a software library is available by contacting the Fujitsu sales representative as required.

*: Encryption function (DES/3DES)

Method to encrypt, and to decrypt plaintext in 64 bits with code and decoding key to 56 bits. (3DES is repeated three times. The key can be set by 168 bits or less.)

• Packet filtering function

The internal feature for L3/L4 packet filtering lets specific data pass or halts them based on address (IP/MAC address) settings. Moreover, the function (multicast address filter function) to receive the data is provided in case of the multicast address registered besides my address, too.

- IEEE 802.3 compliant 10/100M MAC
- MII interface (for full-duplex/half-duplex)
- SMI interface for PHY device control

Note : The filtering function of layer 3/4 (mount on hardware).

This feature determines whether to pass or discard packets when this layer 3 (network layer) IP addresses or layer 4 (transport layer) TCP/UDP port numbers match conditions.

• Outside interface with telecommunication facility (EXTERNAL INTERFACE)

MB91401 is equipped it with the register for the communication and with mass sending and receiving FIFO that achieves a large amount of data sending and receiving. Host functions include processing of data stored in a 3 KByte receive buffer and a 1.5 KByte transmit buffer and stopping of data reception. when the buffers become full.

This enables communication control even during data transmission and reception, thereby improving communication efficiency while reducing the CPU load.

- 8/16 bit data port
- · Equipped with sending and receiving data port control function
- Transfer rate : 133 Mbps (Max)

• General Purpose IO (GPIO)

The interruption can be generated in the I/O port in eight bits according to changing the input signal. Moreover, the I/O setting can be done in each bit.

Memory Interface

It is possible to connect it with an external memory.

• USB Function Controller

- It can not operate as host USB.
- For USB FUNCTION Rev2.0FS
- Double Buffer Specification

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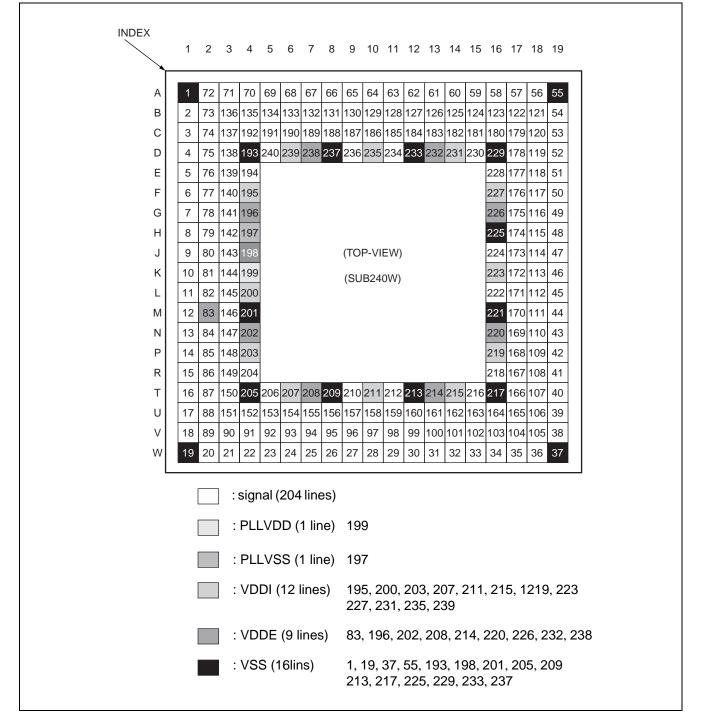
• CARD Interface (CompactFlash)

The CompactFlash interface is a memory and I/O mode correspondence. It corresponds to the I/O of data such as not only the memory card but also the communication cards.

• I²C Interface

- Master/slave sending and receiving
- For standard mode (100 Kbps Max)

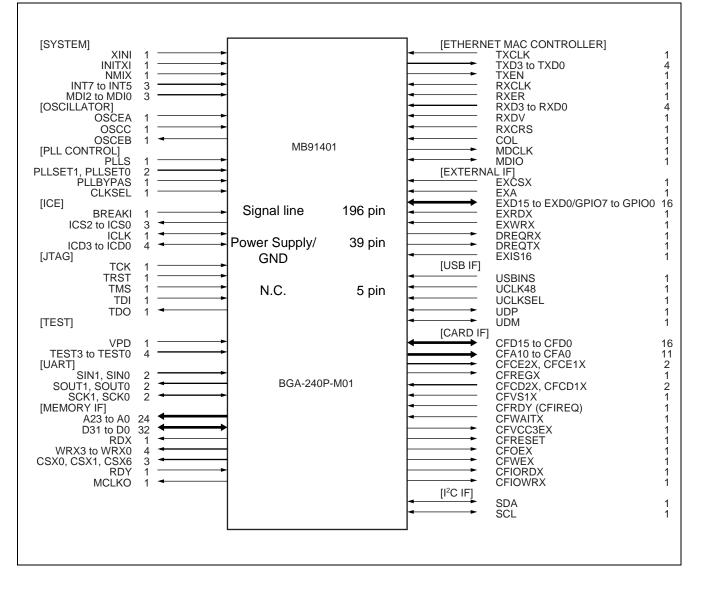
PIN ASSIGNMENT



■ PIN NUMBER TABLE

in Number	Pin name	Pin Number	Pin name	Pin Number	Pin name	Pin Number	Pin name
1	VSS	61	UDP	121	EXD11	181	SDA
2	CFD15	62	CFWEX	122	EXD14	182	USBINS
3	ICLK	63	CFCE1X	123	CFCD2X	183	UDM
4	ICS0	64	CFIORDX	124	UCLKSEL	184	CFRESET
5	TDI	65	CFA1	125	CFWAITX	185	CFREGX
6	UCLK48	66	CFA5	126	N.C.	186	CFA0
7	TMS	67	CFA8	120	CFOEX	187	CFA3
8	XINI	68	CFD0	127	CFCE2X	188	CFA7
							CFA10
9	PLLBYPAS	69	CFD3	129	CFIOWRX	189	
10	OSCEB	70	CFD7	130	CFA2	190	CFD2
11	TEST0	71	CFD10	131	CFA6	191	CFD5
12	OSCEA	72	CFD13	132	CFA9	192	CFD9
13	TEST2	73	CFD14	133	CFD1	193	VSS
14	SCK0	74	ICS2	134	CFD4	194	ICD2
15	SIN0	75	ICS1	135	CFD8	195	VDDI
16	INT5	76	BREAKI	136	CFD11	196	VDDE
17	A3	77	CLKSEL	137	CFD12	197	PLLVSS
18	A2	78	TRST	138	ICD0	198	VSS
19	VSS	79	MDIO	139	ICD1	199	PLLVDD
20	A4	80	MDI0 MDI2	140	ICD3	200	VDDI
20	A4 A7	80	PLLSET0	140	TDO	200	VDDI
21 22		81	TEST1	141	MDI1	201	VSS
	A10					-	
23	A13	83	VDDE	143	VPD	203	VDDI
24	A16	84	TEST3	144	PLLSET1	204	INITXI
25	MCLKO	85	SIN1	145	OSCC	205	VSS
26	A21	86	SOUT0	146	TCK	206	NMIX
27	RDX	87	INT6	147	PLLS	207	VDDI
28	WRX2	88	A6	148	SCK1	208	VDDE
29	CSX0	89	A5	149	SOUT1	209	VSS
30	N.C.	90	A8	150	INT7	210	A0
31	D0	91	A11	151	A9	211	VDDI
32	D2	92	A14	152	A12	212	A1
33	D5	93	A17	153	A15	213	VSS
34	D9	94	A19	154	A18	213	VDDE
35	D3 D12	94	A19 A22	155	A10 A20	214	VDDL
36	D15	96	WRX3	156	A23	216	D8
37	VSS	97	WRX1	157	RDY	217	VSS
38	D17	98	CSX1	158	WRX0	218	D26
39	D18	99	N.C.	159	CSX6	219	VDDI
40	D20	100	D1	160	N.C.	220	VDDE
41	D23	101	D3	161	N.C.	221	VSS
42	D27	102	D6	162	D4	222	MDCLK
43	TXEN	103	D10	163	D7	223	VDDI
44	TXD0	104	D13	164	D11	224	MDIO
45	RXD0	105	D16	165	D14	225	VSS
46	TXCLK	106	D19	166	D22	226	VDDE
40	RXD2	100	D13	167	D25	220	VDDL
47	RXCLK	107	D21	167	D23	228	EXD3/GPIO3
	-				-		
49	EXIS16	109	D28	169	D31	229	VSS
50	EXCSX	110	D30	170	TXD2	230	CFVS1X
51	EXD0/GPIO0	111	TXD1	171	TXD3	231	VDDI
52	EXD4/GPIO4	112	RXD1	172	RXDV	232	VDDE
53	EXD7/GPIO7	113	RXER	173	COL	233	VSS
54	EXD10	114	RXD3	174	DREQRX	234	CFVCC3EX
55	VSS	115	RXCRS	175	DREQTX	235	VDDI
56	EXD12	116	EXA	176	EXWRX	236	CFA4
57	EXD12	117	EXRDX	177	EXD2/GPIO2	237	VSS
58	CFCD1X	118	EXD1/GPIO1	178	EXD6/GPI06	238	VDDE
	SCL	119	EXD5/GPI05	178	EXD9	238	VDDE
59		119		1/9	CVD3	239	VUUI

PIN DESCRIPTION



SYSTEM (9 pin)

Pin name	Pin no.	Polarity	I/O	Circuit	Function/application
XINI	8		IN	D	Clock input pin Input pin of clock generated in clock generator. 10 MHz to 50 MHz frequency can be input.
INITXI	204	Nega- tive	IN	D	Reset input pin This pin inputs a signal to initialize the LSI. When turning on the power supply, apply "0" to the pin until the clock signal input to the CLKIN pin becomes stable. All built-in registers and external pins are initialized, and the built-in PLL is stopped when "0" is asserted to INITXI.
NMIX	206	Nega- tive	IN	D	NMI input pin Non-Maskable Interrupt signal
INT7 INT6 INT5	150 87 16		IN	D	External interrupt input pins These pins input an external interrupt request signal. For external interrupt detection, set the ENIR, EIRR and ELVR registers of the FR core.
MDI2 MDI1 MDI0	80 142 79		IN	D	Mode pins These pins determine the operation mode of the LSI. Always set this bit to "001".

OSCILLATOR (3 pin)

Pin name	Pin no.	Polarity	I/O	Circuit	Function/application
OSCEA	12		IN	G	Crystal oscillation input pin Input pin of crystal oscillation cell.
OSCC	145	Nega- tive	IN	D	Crystal oscillation control input pin Oscillation control pin of crystal oscillation cell. "0" : Oscillation "1" : Oscillation stop
OSCEB	10	_	OUT	G	Crystal oscillation output pin Output pin of crystal oscillation cell.

PLL CONTROL (5 pin)

Pin name	Pin no.	Polarity	I/O	Circuit	Function/application
PLLS	147		IN	D	PLL/through mode (reset) switching input pin "0" : PLL through mode (oscillation stop) "1" : PLL oscillation mode
PLLSET1	144		IN	D	Input clock division ratio select input pin "0" : Input clock direct "1" : Input clock divided by 2
PLLSET0	81		IN	D	Division ratio select input to PLL FB pin "0" : Two dividing frequency is input to the terminal FB. "1" : Four dividing frequency is input to the terminal FB.
PLLBYPAS	9		IN	D	PLL bypass select input pin "0" : PLL used "1" : PLL unused
CLKSEL	77		IN	D	Input clock switching input pin "0" : XINI (External clock) "1" : Built-in OSC generating clock

ICE (9 pin)

Pin name	Pin no.	Polarity	I/O	Circuit	Function/application
BREAKI	76	_	IN	D	Emulator break request pin This pin inputs the emulator break request when an ICE is connected.
ICS2 ICS1 ICS0	74 75 4		OUT	F	Emulator chip status pins These pins output the emulator status when an ICE is connected.
ICLK	3	_	I/O	В	Emulator clock pin This pin serves as the emulator clock pin when an ICE is connected.
ICD3 ICD2 ICD1 ICD0	140 194 139 138		I/O	В	Emulator data pins These pins serve as the emulator data bus when an ICE is connected.

JTAG (5 pin)

Pin name	Pin no.	Polarity	I/O	Circuit	Function/application
тек	146		15.1	Е	JTAG test clock pin
TCK	146		IN		Note : Please input "1" when unused.
TRST	78		IN	Е	JTAG test reset pin
1831	70		IIN		Note : Please input "0" when unused.
TMS	7			E	TAP controller mode select pin
11015			IN		Note : Please input "1" when unused.
					JTAG test data input pin
TDI	5	—	IN	E	JTAG test serial data input pin.
					Note : Please input "1" when unused.
TDO	141		OUT	F	JTAG test data output pin
					JTAG test serial data output pin

TEST (5 pin)

Pin name	Pin no.	Polarity	I/O	Circuit	Function/application
VPD	143	_	IN	_	Mode pin Input "0" to this pin.
TEST3 TEST2 TEST1 TEST0	84 13 82 11		IN	D	Test pin Input "0000" to this pin. Note : Don't set other than above description.

UART (6 pin)

Pin name	Pin no.	Polarity	I/O	Circuit	Function/application
SIN1 SIN0	85 15		IN	D	Serial data input pins Serial data input pin of UART built-in FR core.
SOUT1 SOUT0	149 86		OUT	F	Serial data output pins Serial data output pin of UART built-in FR core.
SCK1 SCK0	148 14	_	I/O	В	Serial clock I/O pins Serial clock input/output pin of UART built-in FR core.

MEMORY IF (66 pin)

Pin name	Pin no.	Polarity	I/O	Circuit	Function/application
A23	156				
A22	95				
A21	26				
A20	155				
A19	94				
A18	154				
A17	93				
A16	24				
A15	153				
A14	92			В	
A13	23				Address output pins 24 bits address signal pin.
A12	152		OUT		
A11	91		001		
A10	22				
A9	151				
A8	90				
A7	21				
A6	88				
A5	89				
A4	20				
A3	17				
A2	18				
A1	212				
A0	210				

(Continued)

Pin name	Pin no.	Polarity	I/O	Circuit	Function/application
D31 D30 D29 D28 D27 D26 D25 D24 D23 D22 D21 D20 D19 D18 D17 D16 D15 D14 D15 D14 D15 D14 D13 D12 D11 D10 D9 D8 D7 D6 D5 D4 D3 D2 D2 D1 D0	$\begin{array}{c} 169\\ 110\\ 168\\ 109\\ 42\\ 218\\ 167\\ 108\\ 41\\ 166\\ 107\\ 40\\ 106\\ 39\\ 38\\ 105\\ 36\\ 165\\ 104\\ 35\\ 164\\ 103\\ 34\\ 216\\ 163\\ 102\\ 33\\ 162\\ 101\\ 32\\ 100\\ 31\\ \end{array}$		I/O	В	Data input/output pins 32 bits data input/output signal pin.
CSX6 CSX1 CSX0	159 98 29	Nega- tive	OUT	В	Chip select output pins 3-bit chip select signal pin. Output the "L" level when accessing to external memory.
RDX	27	Nega- tive	OUT	В	Read strobe output pin Read strobing signal pin. Output the "L" level when read accessing.
WRX3 WRX2 WRX1 WRX0	96 28 97 158	Nega- tive	OUT	В	Write strobing output pins Write strobing signal pin. Output the "L" level when write accessing.
MCLKO	25	_	OUT	F	Memory clock output pin Clock for peripheral resources pin.
RDY	157	Posi- tive	IN	D	External RDY input pin When the external bus is not completed, the bus cycle can be extended by inputting "0".

ETHERNET MAC CONTROLLER (17 pin)

Pin name	Pin no.	Polarity	I/O	Circuit	Function/application
RXCLK	48	_	IN	D	Clock input for reception pin MII sync signal during reception. The frequency is 2.5 MHz at 10 Mbps and 25 MHz at 100 Mbps.
RXER	113	Posi- tive	IN	D	Receive error input pin It is recognized that there is an error in the reception packet when "1" is input from the PHY device at receiving.
RXDV	172	Posi- tive	IN	D	Receive data valid input pin It is recognized that receive data is effective.
RXCRS	115	Posi- tive	IN	D	Career sense input pin The state that the reception or the transmission is done is recognized.
RXD3 RXD2 RXD1 RXD0	114 47 112 45		IN	D	Receive data input pins 4-bit data input from PHY device.
COL	173	Posi- tive	IN	D	Collision detection input pin When TXEN signal is active and "1", the collision is recognized. The collision is not recognized without these conditions.
TXCLK	46		IN	D	Clock input for transfer pin It becomes synchronous of MII when transmitting. The frequency is 2.5 MHz at 10 Mbps and 25 MHz at 100 Mbps.
TXEN	43	Posi- tive	OUT	F	Transfer enable output pin It is shown that effective data is on the TXD bus. It is output synchronizing with TXCLK.
TXD3 TXD2 TXD1 TXD0	171 170 111 44	_	OUT	F	Transfer data output pins 4-bit data bus sent to the PHY device. It is output synchronizing with TXCLK.
MDCLK	222		OUT	F	SMI clock output pin SMI IF clock pin Connect to SMI clock input pin of PHY device.
MDIO	224		I/O	В	SMI data input/output pin Connect to SMI data of PHY device.

EXTERNAL IF (23 pin)

Pin name	Pin no.	Polarity	I/O	Circuit	Function/application
EXCSX	50	Nega- tive	IN	D	External chip select input pin Chip select input pin from external host.
EXA	116	_	IN	D	External address input pin Address input pin from external host. "0" : Register select "1" : FIFO data select
EXD15 EXD14 EXD13 EXD12 EXD11 EXD10 EXD9 EXD8	180 122 57 56 121 54 179 120	_	I/O	В	External data input/output pins The I/O terminal of data bus bit of bit15 to bit8 with an external host.
EXD7/GPIO7 EXD6/GPIO6 EXD5/GPIO5 EXD4/GPIO4 EXD3/GPIO3 EXD2/GPIO2 EXD1/GPIO1 EXD0/GPIO0	53 178 119 52 228 177 118 51		I/O	В	External data/GPIO input/output pins The I/O terminal of data bus bit of bit7 to bit0 with an external host. Note : When EXIS16 "0" input, it becomes the I/O terminal of GPIO7 to GPIO0.
EXRDX	117	Nega- tive	IN	D	External read strobing input pin Read strove input pin from external host
EXWRX	176	Nega- tive	IN	D	External write strobing input pin Write strove input pin from external host
EXIS16	49	_	IN	D	External data bus width select input pin Bit width select pin of EXD "0" : 8 bit (Note : EXD15 to EXD8 are enabled.) "1" : 16 bit
DREQRX	174	Nega- tive	OUT	F	External reception data request output pin Recordable data to reception FIFO is shown.
DREQTX	175	Nega- tive	OUT	F	External transfer data request output pin It is shown that there are data in transmission register and transmission FIFO.

USB IF (5 pin)

Pin name	Pin no.	Polarity	I/O	Circuit	Function/application
UDP	61		I/O	С	USB data D + (differential) pin I/O signal pin on the plus side of the USB data. Use the LSI with 25 Ω to 30 Ω (27 Ω recommended) external series load resistors, 1.5 k Ω pull-up resistors and about 100 k Ω resistors. Input "0" when the USB macro is unused.
UDM	183		I/O	С	USB data D – (differential) pin I/O signal pin on the minus side of the USB data. Use the LSI with 25 Ω to 30 Ω (27 Ω recommended) external series load resistors, 1.5 k Ω pull-up resistors and about 100 k Ω resistors. Input "0" when the USB macro is unused.
USBINS	182		IN	D	USB insert input pin USB socket input detection pin. Be sure to input "0" when not using USB macro.
UCLK48	6		IN	D	48 MHz input (external clock input) pin This pin inputs an external 48-MHz clock signal. The USB macro operates based on this clock. Input the clock with high accuracy (as not only LSI but also a device) more than 2500 ppm. Input "0" when the USB macro is un- used.
UCLKSEL	124		IN	D	USB clock select pin Clock select pin using for USB macro "0" : Using internal clock "1" : Using UCLK48

CARD IF (41 pin)

Pin name	Pin no.	Polarity	I/O	Circuit	Function/application
CFD15 CFD14 CFD13 CFD12 CFD11 CFD10 CFD9 CFD8 CFD7 CFD6 CFD5 CFD4 CFD3 CFD2 CFD0 CFD0 CFD0	2 73 72 137 136 71 192 135 70 240 191 134 69 190 133 68		1/0	В	CF data input/output pins I/O data/status/command signal pin to CompactFlash card side
CFA10 CFA9 CFA7 CFA6 CFA5 CFA4 CFA3 CFA2 CFA1 CFA0	189 132 67 188 131 66 236 187 130 65 186		OUT	В	CF address 10 to 0 output pins Address output CFA10 to CFA0 pins to CompactFlash card side
CFCE2X	128	Nega- tive	OUT	В	CF card enable output pin Byte access output pin to CompactFlash card side Note : Supported for access to CFD7 to CFD0. When "L" level is output, odd number byte access of the word is shown.
CFCE1X	63	Nega- tive	OUT	В	CF card enable output pin Byte access output pin to CompactFlash card side Note : Supported for access to CFD7 to CFD0. When "L" level is output at word access, even number byte access of the word is shown. When the byte is accessed, the even number byte and odd number byte access become possible because CFA0 and CFCE2X are combined and used by it.
CFREGX	185	Nega- tive	OUT	В	CF Attribute/Common switching output pin Attribute/Common switching output pin to CompactFlash card side "H" : Common Memory select "L" : Attribute Memory select
CFCD2X	123	Nega- tive	IN	E	Card connection detect input pin : CFCD2X Checking connection pin of the socket and CompactFlash card. It is shown that the CompactFlash card was connected when this signal and CFCD1X are both input by "0".

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Pin name	Pin no.	Polarity	I/O	Circuit	Function/application
CFCD1X	58	Nega- tive	IN	E	Card connection detect input pin : CFCD1X Checking connection pin of the socket and CompactFlash card. It is shown that the CompactFlash card was connected when this signal and CFCD2X are both input by "0".
CFVS1X	230	Nega- tive	IN	E	CF side GND input pin GND level detection pin from CompactFlash side. The "0" input to the pin assumes that the CompactFlash card can operate at 3.3 V, setting the CFVCC3EX pin to the "L" level.
CFRDY (CFIREQ)	60	Posi- tive (Nega- tive)	IN	E	CF ready input pin : memory card Ready input pin from CompactFlash memory card side "1" : Ready "0" : Busy (CF interrupt : I/O card) Interrupt request pin of CompactFlash I/O card. It is shown the interrupt request was done from the I/O card when input to this signal by "0".
CFWAITX	125	Nega- tive	IN	E	 Cycle wait input pin during CF execution Cycle wait input pin from CompactFlash card side "0": It is shown that there is a wait demand at the cycle under execution. "1": It is shown that there is no wait demand at the cycle under execution.
CFVCC3EX	234	Nega- tive	OUT	в	CF3.3 V power enable output pin Outputs "L" level when the CompactFlash card is operable at 3.3 V. The output signal enables 3.3-volt power supply to the CompactFlash card. The pin outputs "L" level only when the CFVS1X pin detects "0"; otherwise, the pin outputs "H".
CFRESET	184	Posi- tive	OUT	A	CF reset output pin Reset output pin to CompactFlash card side. CompactFlash is reset at "H" output.
CFOEX	127	Nega- tive	OUT	В	CF read strobe output pin Read strove output pin to CompactFlash card (memory mode and Attribute memory area)
CFWEX	62	Nega- tive	OUT	В	CF register write output pin Write clock output pin to CompactFlash card (register write and Card Configuration Register area). The register write is executed at the rising edge from "L" to "H".
CFIORDX	64	Nega- tive	OUT	В	CFIO read strobing output pin Read strove output pin to CompactFlash card (I/O mode)
CFIOWRX	129	Nega- tive	OUT	В	CFIO write strobing output pin Write strove output pin to CompactFlash card (I/O mode)

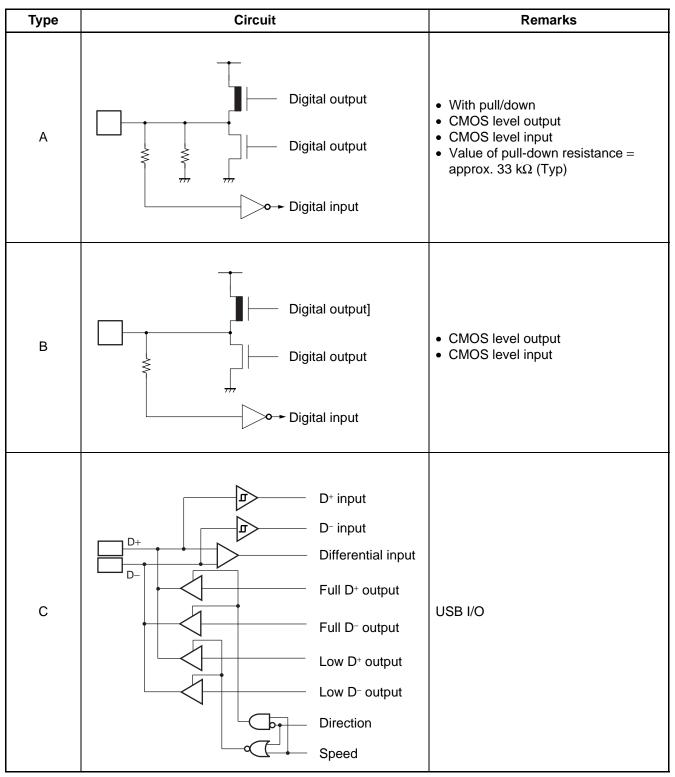
I²C IF (2 pin)

Pin name	Pin no.	Polarity	I/O	Circuit	Function/application
SDA	181	_	I/O	В	Serial data line input/output pin I²C bus data I/O pin
SCL	59		I/O	В	Serial clock line input/output pin I²C bus clock I/O pin

Power Supply/GND (39 pin)

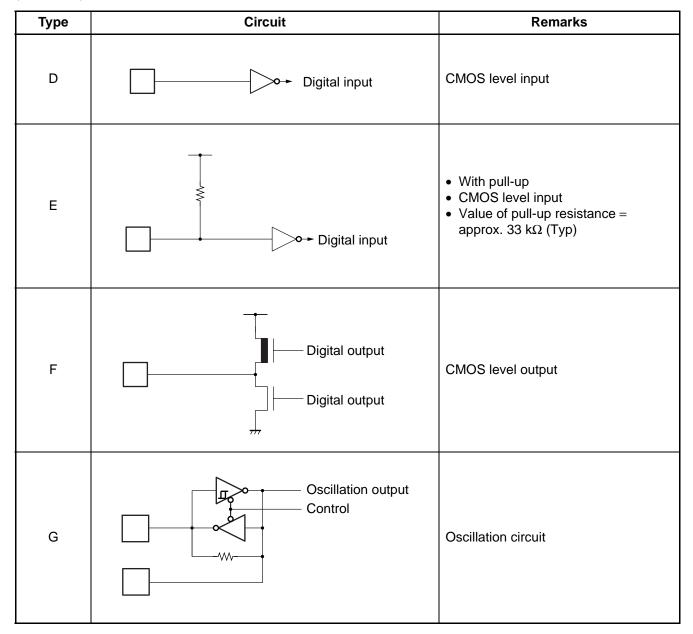
Pin name	Pin no.	Polarity	I/O	Circuit	Function/application
PLLVDD	199	_	Power supply	V-E	APLL dedicated power supply pin This pin is for 1.8 V power supply pin.
PLLVSS	197		GND	V-S	APLL dedicated GND Pin
VDDE	83 196 202 208 214 220 226 232 238		Power supply	V-E	3.3 V power supply pin
VDDI	195 200 203 207 211 215 219 223 227 231 235 239		Power supply	V-E	1.8 V power supply pin
VSS	1 19 37 55 193 198 201 205 209 213 217 221 225 229 233 237		GND	V-S	GND Pin

■ I/O CIRCUIT TYPE



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■ HANDLING DEVICES

Preventing Latch-up

When a voltage that is higher than V_{DDE} and a voltage that is lower than V_{SS} are impressed to the input terminal and the output terminal in CMOS IC or the voltage that exceeds ratings between V_{DDE} to V_{SS} is impressed, the latch-up phenomenon might be caused. If latch-up occurs, the supply current increases rapidly, sometimes resulting in thermal breakdown of the device. Use meticulous care not to let any voltage exceed the maximum rating during device operation.

Separation of power supply pattern

Analog PLL (APLL at the following) is installed in this LSI. The power supply for VCO and for digital is separated in LSI so that the oscillation characteristic of APLL may receive the influence of power supply variation.

Therefore, the power supply is recommended to be separated also on the mounting base.

• Separation of power supply pattern (recommended)

Take measures to reduce impedance, for example, by using as wide a power pattern as possible. The recommendation example is shown as follows.

For two power supplies (for digital and for VCO)

It is advisable to provide a digital power-supply (a) and VCO power-supply (b) and connect them to the LSI's equivalents, respectively.

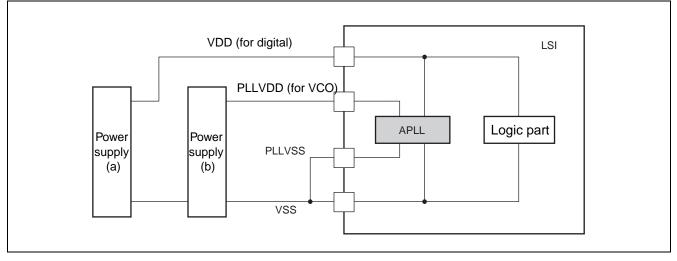
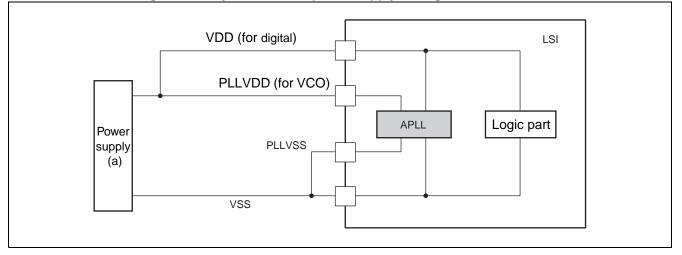


Figure For 2-power supply (for digital and for VCO)

· For the common power supply

To share a single power-supply for digital and VCO uses, it is advisable to separate the output into the digital and VCO wiring patterns and connect them to the LSI.

Figure When you share the power supply for digital and for VCO



Treatment of the unused pins

Leaving unused input pins open results in a malfunction, so process the pull-up or pull-down.

Treatment of OPEN pins

Be sure to use open pins in open state.

Treatment of output pins

A large current may flow to an output pin left connected to the power-supply, another output pin, or to a high capacitance load. Leaving the output pin that way for an extended period of time degrades the device. Use meticulous care in using the device not to exceed the absolute maximum rating.

About Mode (MDI2 to MDI0, VPD) pin and Test (TEST3 to TEST0) pin

Connect these pins directly to VDDE or VSS. To prevent the device from entering test mode accidentally due to noise, minimize the lengths of the patterns between individual mode pins and VDDE or VSS on the PC board as possible and connect them with as low an impedance as possible.

About power supply pins

In products with multiple VDDE, VDDI or VSS pins, the pins of the same potential are internally connected in the device to avoid abnormal operations including latch-up. However you must connect the pins to external power supply and a ground line to lower the electro-magnetic emission level to prevent abnormal operation strobe signals caused by the rise in the ground level, and to conform to the total output current rating.

The power pins should be connected to VDDE, VDDI and VSS of this device at the lowest possible impedance from the current supply source.

It is also advisable to connect a ceramic bypass capacitor of approximately 0.1 μ F between VDDE and VSS, and between VDDI and VSS near this device.

Crystal Oscillator Circuit

Noise near the OSCEA terminal may cause the MB91401 to malfunction.

Design the circuit board so that OSCEA terminal, OSCEB terminal and the crystal oscillator, and the bypass capacitor to ground are located as close to the device as possible.

It is strongly recommended to design the PC board artwork with the OSCEA terminal and OSCEB terminal surrounded by ground plane because stable operation can be expected with such a layout.

■ CONNECTED SPECIFICATION OF MB91401 AND ICE

Recommended type and circuit configuration of the emulator interface connector mounting on the user system, attention when designing and wiring regulation are shown.

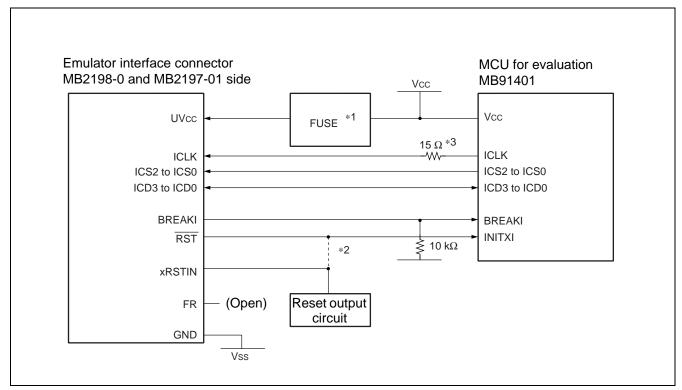
When the flat cable is used, the combination of the connectors with housing should be selected.

Recommended connector type

Attached cable	Part number	Remarks
FPC cable	FH10A-30S-1SH (Maker : Hirose Electric Co., Ltd.)	With latch

• Circuit composition

Please put the dumping resistance 15 Ω in the series in the ICLK terminal signal because of the stability of operation when connecting it with ICE. Resistance must be mounted near the terminal ICLK of this LSI when you design the printed wiring board.



*1 : Use the line (inter connect) to flow the rating current or more.

*2 : The change circuit might become necessary, and refer to "Precaution when designing".

*3 : Mount resistance near the terminal ICLK of MB91401.

• Precaution when designing

When evaluation MCU on the user system is operated in the state that the emulator is not connected, should be treated as follow each input terminal of evaluation MCU connected with the emulator interface on the user system.

Therefore, note that the switch circuit etc, might become necessary in the user system when you design.

The terminal processing in each emulator interface is shown as follows.

Pin treatment of emulator interface (DSU-3)

Evaluation MCU terminal name	Pin treatment
RST	To be connected the RST terminal with the reset output circuit in the user system.
Others	To open.

Emulator interface wiring regulations

Signal line name	Wiring regulations
ICLK ICS2 to ICS0 ICD3 to ICD0 BREAKI	 The total wiring length of each signal (From evaluation MCU pin to the emulator interface connector pin) is made within 50 mm. The difference of the total wiring length of each signal makes within 2 cm and the total wiring length of ICLK is the shortest.
UVcc	 Wire the pattern with capacity more than the ratings current. Each power supply and GND may cause a short-circuit or reverse connection in between by a wrong connection of a probe. Insert a protection circuit such as a fuse into each power supply pattern to safeguard it.
GND	Connect directly with a power supply system pattern such as grandopran.

• Reference document

Please match and refer to the following manual for the connection with ICE.

- DSU-FR Emulator MB2198-01 Hardware Manual
- FR20/30 series MB2197-01 Hardware Manual

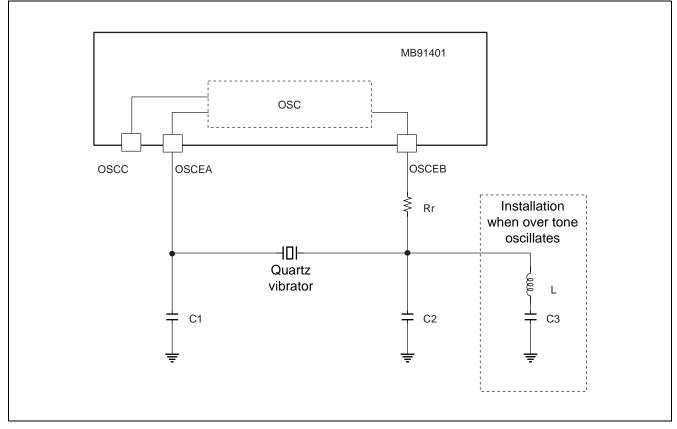
JTAG

The JTAG function is installed in this LSI.

Note that the terminal INITXI should be input in "L" when using JTAG.

Notes when quartz vibrator is mounted

The crystal oscillation circuit built into this LSI operates by the following compositions.



• Pin description

Pin name	Function
OSCC	Oscillation control terminal of crystal oscillation cell (OSC)
OSCEA	Input terminal of crystal oscillation cell (OSC)
OSCEB	Output terminal of crystal oscillation cell (OSC)

When OSCCL is input, the OSCEA and OSCEB oscillate at the natural frequency of the crystal oscillator and propagated into the LSI.

• Circuit constant on external substrate

Circuit constants	Description
C1, C2, C3	External load capacity
L	Inductance
Rr	Dumping resistance (addition if necessary)

• Reference Value

Oscillation frequency	C1, C2	C3	L	Rr
to 30 MHz	5 pF to 33 pF	None	None	None
20 MHz to 50 MHz	5 pF to 15 pF	10 nF approx.	1 μH approx.	None

It is necessary to add C3/L depending on a basic wave and the over tone characteristic of the oscillator of the 20 MHz to 30 MHz belt.

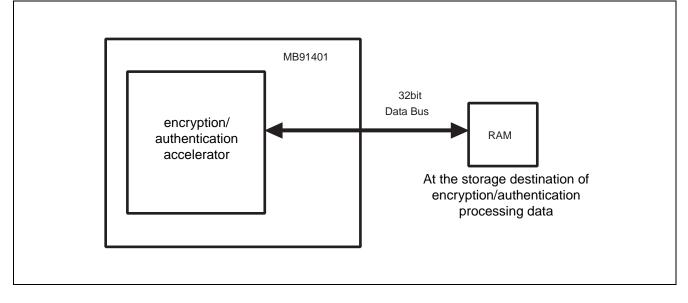
Note : These reference values are standards. The constant changes according to the characteristic of the quartz vibrator used. Therefore, we will recommend the initial evaluation that uses the evaluation sample to the decision of the circuit constant. Please contact FUJITSU representatives about the evaluation sample.

• Notes when encryption/authentication accelarator is used

When using the encryption/authentication installed in this LSI, it is necessary to the following notes.

32-bit data bus

The encryption/authentication accelerator fetches data from the area storing data to be subject to encryption/ authentication and encrypts or authenticates the data without CPU intervention. In the encryption processing, write is done in the area where it wants to store the data after the encryption is processed.



Holding request withdrawal demand function OFF

When accessing to the storage destination of encryption/authentication processing data, the encryption/authentication accelerator should hold an internal bus of this LSI.

Therefore, when the encryption/authentication accelerator are used, it should be set that the holding request withdrawal doesn't demand.

Please set the HRCL register that sets the interrupt level that becomes the standard of the holding request withdrawal demand generation to "10000" in the FR core.

For NMIs, the hold request cancel request occurs regardless of the HRCL register setting. When the encryption/ authentication accelerator is used, therefore, NMI input may cause encryption/authentication to fail to result correctly. In that case, the correspondence said that it will execute the encryption/authentication processing under execution again is necessary.

Notes as device

Treatment of Unused Input Pins

It causes the malfunction that the unused input terminal is made open, and do the processing such as 1 stack or 0 stacks.

About Mode pins (MDI2 to MDI0)

Connect these pins with the input buffer by 1 to 1 to prevent the malfunction by the noise, and connect directly to VDD or VSS outside of ASIC.

Operation at start-up

Specify set initialization reset (INIT) with the terminal INITXI when you turn on the power supply.

Moreover, connect "L" level input to the terminal INITXI until the input clock is steady.

About watch dog timer

The watchdog timer function of this macro monitors a program to check whether it delays a reset within a certain period of time. If the program runs out of control and fails to delay the reset, the watchdog timer function resets the CPU.

Therefore, it keeps operating until reset is specified when the watchdog timer function is made effective once.

Exceptionally, the reset postponement is automatically done under the condition that the program execution of CPU stops. Refer to the paragraph of the function explanation of the watchdog timer for the condition of applying to this exception.

There is a possibility that watchdog reset is not generated when entering the above-mentioned state by the reckless driving of the system. In that case, please specify reset (INIT) from external INITX terminal.

Restrictions

- Clock control block
 - Secure the clock stability waiting time at "L" input to INITXI.
 - When entering the standby mode, use the following sequences after using the synchronous standby mode (TBCR:set at the bit8 SYNCS bit of timebase counter control register).

`		5,
(LDI	#value_of_standby, R0)	; Value_of standby is write data to STCR.
(LDI	#_STCR, R12)	; _STCR is address (481H) of STCR.
STB	R0, @R12	; Write to standby control register (STCR).
LDUB	@R12, R0	; STCR read for synchronous standby
LDUB	@R12, R0	; Dummy re-read of STCR
NOP		

In addition, set the I-flag and the ILM and ICR registers to branch to an interrupt handler when the interrupt handler triggers the microcontroller to return from the standby mode.

- Please do not do the following when the monitor debugger is used.
- Please do not set the break point to the above-mentioned instruction row.

CPU

- The instruction fetch is not done from D-bus, and does not set the code area on D-bus RAM.
- Set neither stack area nor the vector table on the instruction RAM.
- The following operations may be performed when the instruction immediately followed by a DIVOU/DIVOS instruction is (a) halted by a user interrupt or NMI, (b) single-stepped, or (c) breaks in response to a data event or emulator menu:
 - (1) The D0 and D1 flags are updated in advance.
 - (2) An EIT handling routine (user interrupt, NMI, or emulator) is executed.
 - (3) Upon returning from the EIT, the DIVOU/DIVOS instruction is executed and the D0 and D1 flags are updated to the same values as in (1).
- The following operations are performed when the ORCCR/STILM/MOVRi and PS instructions are executed.
 - (1) The PS register is updated in advance.
 - (2) Executing of EIT processing routine (user interrupt NMI)
 - (3) Upon returning from the EIT, the above instructions are executed and the PS register is updated to the same value as in (1).
- Since some instructions manipulate the PS register earlier, the following exceptions may cause the interrupt handler to break or the PS flag to update its display setting when the debugger is being used. As the micro-controller is designed to carry out reprocessing correctly upon returning from such an EIT event in either case, it performs operations before and after the EIT as specified.
- 1. When (a) user interrupt and NMI are accepted or (b) step is executed or (c) break is done by the data event or the menu of the emulator in the instruction immediately before the instruction of DIV0U/DIV0S, the following operation might be done.
 - (1) The D0 and D1 flags are updated in advance.
 - (2) An EIT handling routine (user interrupt, NMI, or emulator) is executed.

(1) Upon returning from the EIT, the DIVOU/DIVOS instruction is executed and the D0 and D1 flags are updated to the same values as in (3).

- 2. When ORCCR, STILM, MOV Ri, and PS each instruction is executed to permit interrupt with the user interrupt and the NMI factor generated, the following operation is done.
 - (1) The PS register is updated in advance.
 - (2) The EIT processing routine (user interrupt, NMI or emulator) is executed.
 - (3) Upon returning from the EIT, the above instructions are executed and the PS register is updated to the same value as in (1).
- Do not access the data to the cache memory at the control register of the instruction cash and RAM mode immediately before the instruction of RETI.
- If one of the instructions listed below is executed, the SSP or USP* value is not used as the R15 value and, as a result, an incorrect value is written to memory.
- Only ten following kinds of instructions that specify R15 as Ri correspond.

AND	R15, @Rj	ANDH	R15, @Rj	ANDB	R15, @Rj
OR	R15, @Rj	ORH	R15, @Rj	ORB	R15, @Rj
EOR	R15, @Rj	EORH	R15, @Rj	EORB	R15, @Rj
XCHB	@Rj, R15				

* : As for R15, there are no realities. When R15 is accessed from the program, SSP or USP is accessed by the state of "S" flag of the PS register. Please specify general registers other than R15 when ten above-mentioned instructions are described by the assembler.

- External bus interface
 - When the bus width of the area set up as little endian is 32-bit, confine to word (32-bit) access when accessing the relevant area.
 - When enabling prefetch to the area set to the Little endian, give the access to the corresponding area as word (32 bits) access limitation. In the byte and the half word access, it is not possible to access it correctly.

• DMA

• Do not transfer DMA to instruction RAM.

• Bit Search Module

• BSD0, BSD1, and the BDSC register are only the word accesses.

NOTES OF DEBUG

Step execution of RETI instruction

In an environment where interrupts frequently occur during single-step execution, only the relevant interrupt processing routines are executed repeatedly during single-step execution of the RETI instruction. This will prevent the main routine and low-interrupt-level programs from being executed.

Do not execute step of RETI instruction for escape.

When the relevant interrupt routine no longer requires being debugged, disable the relevant interrupt and perform debugging.

Operand break

Do not set the access which is used for area, including the address of system stack pointer, to the target of data event break.

Interrupt handler to NMI request (tool)

To prevent the malfunction because of the noise problem of DSU pin when ICE is unconnected, the following programs are added to the interrupt handler by the cause flag, which is only set by the break request from ICE. ICE can be used even if this program is added.

Location to added

The following interrupt handler

Interrupt resource	: NMI request (tool)
Interrupt number	: 13 (decimal), 0D (hexadecimal)
Offset	: 3С8н
TBR is default address.	: 000FFFC8н

Additional program

STM (R0, R1) LDI #B00H, R0 ; B00H is address of the break resource register. LDI #0, R1 STB R1, @R0 ; Clear the break resource register. LDM (R0, R1) RETI

Trace mode

If the trace mode is set to "Full trace mode" during debug (in full trace mode, built-in FIFO is used as output buffer, the trace memory of the main body of ICE is used, and the trace data lost is not occurred), the electric current is increased and D-busDMA access may be lost.

Also, the trace data lost may be occurred.

To take the measures, do not set full trace mode.

Simultaneous generation of a software break and a user interrupt/NMI

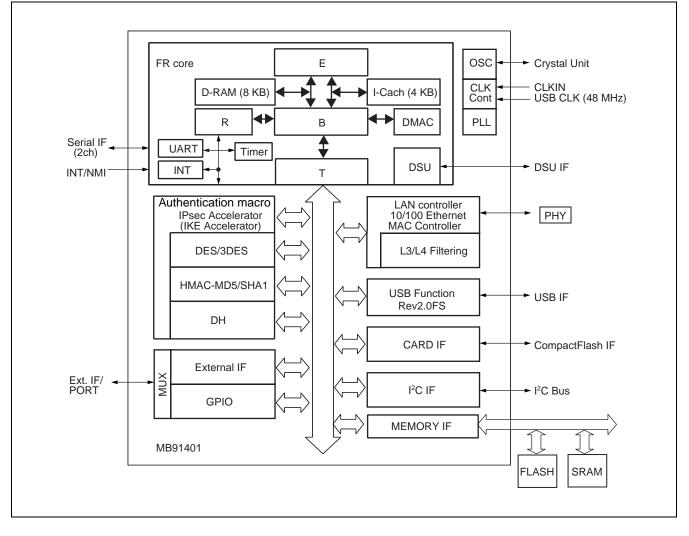
When a software break and a user interrupt/NMI occur simultaneously, the emulator debugger may react as follows.

• The debugger stops pointing to a location other than the programmed breakpoints.

• The halted program is not re-executed correctly.

When these problems are occurred, not only the software break, the hardware break should also be used. Do not set the break to the corresponding location when using monitor debugger.





FR core : CPU, U-Timer, UART, Timer, Interrupt controller, DMAC, Bit search, External interrupt, Memory_IF, Data-RAM, Cache, Bus controller

Peripheral resources : LAN, External_IF, GPIO, Card, Encryption/Authentication, I²C, USB (Peripheral resource is connected to bus of bus controller.)

■ MEMORY SPACE

• Memory space

The FR family has 4 GByte of logical addresses (2³² address) which can be linearly accessed by the CPU.

Direct Addressing Areas

The following address space areas are used as I/O areas.

These areas are called direct addressing areas, in which the address of an operand can be specified directly during an instruction.

The direct addressing area varies as shown below depending on the size of access data:

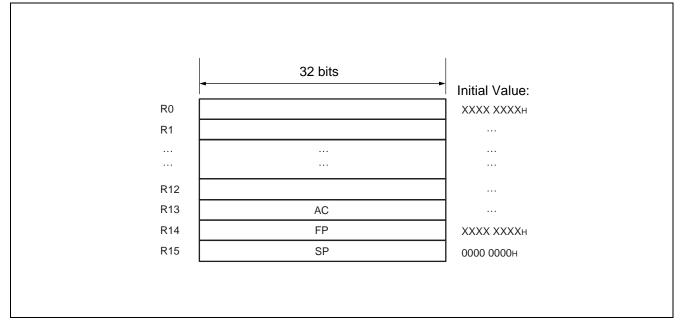
 \rightarrow byte data access $$:0-0FF_{\mbox{\scriptsize H}}$$

- \rightarrow half word data access $$: 0-1FF_{H}
- \rightarrow word data access : 0-3FF_H
- Memory Map

The memory space of the macro consists of the following areas.

Direct Addressing Areas	I/O	0000 0000н
Refer to I/O Map	I/O	0000 0400н
	I-bus RAM 4 KB (and its mirror)	0001 0000н
	Access disallowed area	0002 0000н
	D-bus RAM 8 KByte	0003 F800н
		0004 0000н
	External area	
		FFFF FFFFH

■ GENERAL PURPOSE REGISTERS



Registers R0 to R15 are general-purpose registers. The registers are used as the accumulator and memory access pointers for CPU operations.

Of these 16 registers, the registers listed below are intended for special applications, for which some instructions are enhanced.

R13: Virtual accumulator R14: frame pointer R15:Stack pointer

The initial values of R0 to R14 after a reset are indeterminate. R15 is initialized to 0000000H (SSP value).

MODE SETTINGS

The FR family uses the mode pins (MDI2 to MDI0) and the mode register (MODR) to set the operation mode.

Mode Pins

Three mode pins MDI[2], MDI[1], and MDI[0] are used to specify a mode vector fetch or test mode.

Mode pins	- Mode name	Reset vector	Remarks	
MDI2 to MDI0	woue name	access area	Keinarks	
0 0 0	Reserved	—		
001	external ROM mode vector	External	Bus width is set by the mode data.	
0 1 0	User circuit test		FR stops (with clock signal supplied).	
0 1 1	Reserved			
100	Reserved			
101	Reserved			
1 1 0	Reserved			
1 1 1	Reserved			

Setting MDI2 to MDI0 to "010", USRTEST is set to "1" and the device operates in the user circuit test mode. The FR71 core is suspended in the user circuit test mode while SYSCLK and MCLKO are operating. The reserved modes include the FR71 core test mode. In this case, the signal at the FRTEST pin becomes "1" and enters the FR71 core test mode. If the FRTEST pin = "1", that circuit configuration is required which allows the separately defined pins of the FR71 core to be controlled and monitored from the outside of the chip.

• Mode Register (MODR)

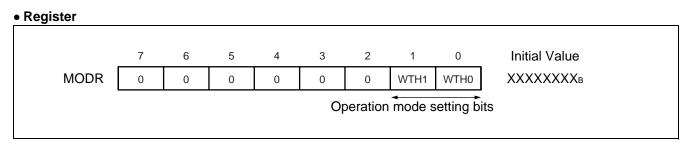
The data written to the mode register (MODR) by hardware using a mode vector fetch is called mode data.

When this register is set by hardware, the CPU operates in the operation mode corresponding to the register setting.

The mode register is set only by an INIT-level reset cause. The user program cannot access this register.

However, as an exception, when the macro shifts to emulation mode by INTE instruction, or shifts to emulation mode by a break at a debug using ICE, this register is mapped at 0000_07FD_H. Select this function when using ICE, perform the mode data setting before the program loading by writing a appropriate value to this register.

Note : No data is existed in the address (0000_07FF_H) in the mode register of the FR family.



[bit7 to bit2] Reserved bit

Be sure to set this bit to "000000". Setting them to any other value may result in an unpredictable operation.

[bit1, bit0] WTH1, WTH0 (Bus width setting bits)

These bits specify the bus width. The value of the bits is set in the DBW1 and DBW0 bits in ACR0 (CSO area). Set these bits to a value other than "11".

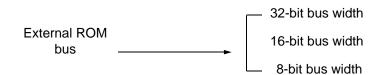
WTH1	WTH0	Function	Remarks
0	0	8-bit bus width	External bus mode
0	1	16-bit bus width	External bus mode
1	0	32-bit bus width	External bus mode
1	1	Setting disabled	

Operation mode

In the operation mode, there are a bus mode and an access mode.

Bus mode

Access mode



Bus mode

In bus mode, the operations of internal ROM and the external access functions are controlled according to the mode setting pins (MD2 to MD0) and the values of mode data.

Although the FR71 architecture supports this bus mode, this macro cannot use the single-chip or internal ROM/ external bus mode but can use the external ROM/external bus mode only.

Access mode

Access mode indicates the mode that controls the external data bus width, and is specified by the WTH1/WTH0 bits, and the DBW1/DBW0 bits within ACR0 to ACR7 (Area Configuration Registers).

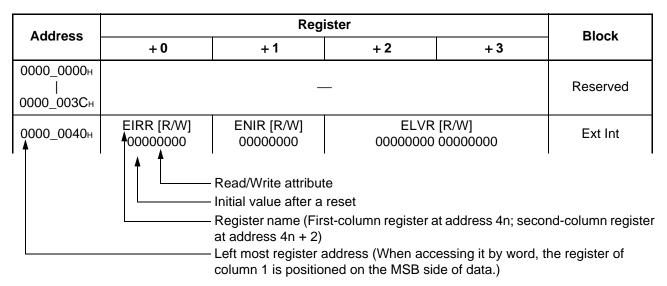
Bus mode

The FR family has three bus modes described below. Please refer to "■ MEMORY SPACE" for details.

I/O MAP

This shows the location of the various peripheral resource registers in the memory space.

[How to read the table]



Note : Initial values of register bits are represented as follows :

- "1" : Initial Value "1"
- "0" : Initial Value "0"
- "X" : Initial Value "X"
- "-" : Access prohibited in reserved area.

Address		Diesk				
	+ 0	+ 1	+ 2	+ 3	Block	
0000_0000н to 0000_003Сн		Reserved				
0000_0040н	EIRR [R/W] 00000000	ENIR [R/W] 00000000		[R/W] 00000000	Ext Int	
0000_0044н	DICR [R/W] 0	HRCL [R/W] 0-11111	_	_	DLYI/I-unit	
0000_0048н	TMRLR0 XXXXXXXX		TMR0 XXXXXXXX	[R] XXXXXXXX	Reload Timer 0	
0000_004Сн			TMCSR0 0000	[R/W] 00000000		
0000_0050н	TMRLR1 XXXXXXXX		TMR1 XXXXXXXX	[R] XXXXXXXX	Reload Timer 1	
0000_0054н			TMCSR1 0000	[R/W] 00000000		
0000_0058н	TMRLR2 [W]TMR2 [R]XXXXXXXX XXXXXXXXXXXXXXXXX XXXXXXXX		Belood Timer 2			
0000_005Cн	_	_	TMCSR2 0000	[R/W] 00000000	Reload Timer 2	

A daha a a		Plaak			
Address	+ 0	+ 1	+ 2	+ 3	Block
0000_0060н	SSR0 [R/W] 00001-00	SIDR0 [R/W] XXXXXXXX	SCR0 [R/W] 00000100	SMR0 [R/W] 000-0-	UART0
0000_0064н	UTIM0 [R] 00000000	(UTIMR0 [W]) 00000000	DRCL0 [W]	UTIMC0 [R/W] 000001	U-TIMER0
0000_0068н	SSR1 [R/W] SIDR1 [R/W] 00001-00 XXXXXXXX		SCR1 [R/W] 00000100	SMR1 [R/W] 000-0-	UART1
0000_0048н	UTIM1 [R] 00000000	(UTIMR1 [W]) 00000000	DRCL1 [W]	UTIMC1 [R/W] 000001	U-TIMER1
0000_0070н to 0000_01FCн		_	_		Reserved
0000_0200н	00	DMACA0 000000 00000000	[R/W] 0000XXXX XXXX	xxxx	
0000_0204н	00	DMACB0 000000 00000000	[R/W] 00000000 00000000		
0000_0208н	DMACA1 [R/W] 00000000 00000000 0000XXXX XXXXXXXX				
0000_020Сн	DMACB1 [R/W] 00000000 00000000 00000000 00000000			000	
0000_0210н	00	DMACA2 000000 00000000	[R/W] 0000XXXX XXXXXXXX		DMAC
0000_0214н	00	DMACB2 000000 00000000	[R/W] 00000000 00000000		
0000_0218н	00	DMACA3 000000 00000000	[R/W] 0000XXXX XXXXXXXX		
0000_021Cн	00	DMACB3 000000 00000000	[R/W] 00000000 00000000		
0000_0220н	DMACA4 [R/W] 00000000 0000000 00000XXXX XXXXXXXX				
0000_0224н	DMACB4 [R/W] 00000000 00000000 0000000000000000000				
0000_0228н to		-	_		Reserved
0000_023Сн 0000_0240н	DMACR [R/W] 0XX00000 XXXXXXX XXXXXXX XXXXXXXX			DMAC	
0000_0244н to 0000_0300н	0.00				Reserved
0000_0304н				ISIZE [R/W] 10	Instruction Cache

(Continued)

Address		Block				
Address	+ 0	+ 1	+ 2	+ 3	BIOCK	
0000_0308н to 0000_03E0н		Reserved				
0000_03E4н		_		ICHRC [R/W] 0-000000	Instruction Cache	
0000_03E8н to 0000_03ECн		-	_		Reserved	
0000_03F0н	XXXX	BSD0 XXXX XXXXXXXX	[W] XXXXXXXX XXX	xxxxx		
0000_03F4н	xxxx	BSD1 XXXX XXXXXXXX	[R/W] XXXXXXXX XXX	xxxxx	Bit Search	
0000_03F8н	xxxx	BSDC XXXX XXXXXXXX	[W] XXXXXXXX XXX	xxxxx	Module	
0000_03FCн	xxxx	BSRR XXXX XXXXXXXX	[R] XXXXXXXX XXX			
0000_0400н to 0000_043Cн		-	_		Reserved	
0000_0440н	ICR00[R/W] 11111	ICR01[R/W] 11111	ICR02[R/W] 11111	ICR03[R/W] 11111	-	
0000_0444н	ICR04[R/W] 11111	ICR05[R/W] 11111	ICR06[R/W] 11111	ICR07[R/W] 11111		
0000_0448н	ICR08[R/W] 11111	ICR09[R/W] 11111	ICR10[R/W] 11111	ICR11[R/W] 11111		
0000_044Сн	ICR12[R/W] 11111	ICR13[R/W] 11111	ICR14[R/W] 11111	ICR15[R/W] 11111		
0000_0450н	ICR16[R/W] 11111	ICR17[R/W] 11111	ICR18[R/W] 11111	ICR19[R/W] 11111	-	
0000_0454н	ICR20[R/W] 11111	ICR21[R/W] 11111	ICR22[R/W] 11111	ICR23[R/W] 11111	Interrupt Control Unit	
0000_0458н	ICR24[R/W] 11111	ICR25[R/W] 11111	ICR26[R/W] 11111	ICR27[R/W] 11111		
0000_045Cн	ICR28[R/W] 11111	ICR29[R/W] 11111	ICR30[R/W] 11111	ICR31[R/W] 11111		
0000_0460н	ICR32[R/W] 11111	ICR33[R/W] 11111	ICR34[R/W] 11111	ICR35[R/W] 11111		
0000_0464н	ICR36[R/W] 11111	ICR37[R/W] 11111	ICR38[R/W] 11111	ICR39[R/W] 11111		
0000_0468н	ICR40[R/W] 11111	ICR41[R/W] 11111	ICR42[R/W] 11111	ICR43[R/W] 11111		

(Continued)

Address		Plaak			
Address	+ 0	+ 1	+ 2	+ 3	- Block
0000_046Сн	ICR44[R/W] 11111	ICR45[R/W] 11111	ICR46[R/W] 11111	ICR47[R/W] 11111	Interrupt Contro Unit
0000_0470н to 0000_047Cн	_		_	_	Reserved
0000_0480н	RSRR [R/W] 10000000*2	STCR [R/W] 00110011* ²	TBCR [R/W] 00XXXX00*1	CTBR [R/W] XXXXXXXX	Clock Control
0000_0484н	 Access disallowed	WPR [W] XXXXXXXX	DIVR0 [R/W] 00000011*1	DIVR1 [R/W] 00000000	Unit
0000_0488н to 0000_063Fн		-	_		Reserved
0000_0640н	ASR0 00000000		ACR0 1111**00	[R/W] 00000000*3	
0000_0644н	ASR1 XXXXXXXX	[R/W] XXXXXXXX	ACR1 XXXXXXXX	[R/W] XXXXXXXX	
0000_0648н	ASR2 XXXXXXXX	[R/W] XXXXXXXX	ACR2 XXXXXXXX	[R/W] XXXXXXXX	
0000_064Cн	ASR3 XXXXXXXX	[R/W] XXXXXXXX	ACR3 XXXXXXXX	[R/W] XXXXXXXX	
0000_0650н	ASR4 XXXXXXXX	[R/W] XXXXXXXX	ACR4 XXXXXXXX	[R/W] XXXXXXXX	
0000_0654н	ASR5 XXXXXXXX	[R/W] XXXXXXXX	ACR5 XXXXXXXX	[R/W] XXXXXXXX	
0000_0658н	ASR6 XXXXXXXX	[R/W] XXXXXXXX	ACR6 XXXXXXXX	[R/W] XXXXXXXX	
0000_065Cн	ASR7 XXXXXXXX	[R/W] XXXXXXXX	ACR7 XXXXXXXX	[R/W] XXXXXXXX	Memory IF
0000_0660н	AWR0 01111111		AWR1 XXXXXXXX	[R/W] XXXXXXXX	
0000_0664н	AWR2 XXXXXXXX	[R/W] XXXXXXXX	AWR3 XXXXXXXX	[R/W] XXXXXXXX	
0000_0668н	AWR4 XXXXXXXX	[R/W] XXXXXXXX	AWR5 XXXXXXXX	[R/W] XXXXXXXX	
0000_066Сн	AWR6 XXXXXXXX	[R/W] XXXXXXXX	AWR7 XXXXXXXX	[R/W] XXXXXXXX	
0000_0670н	MCRA XXXXXXXX	MCRB XXXXXXXX	_	_	
0000_0674н		-			1
0000_0678н	IOWR0 [R/W] XXXXXXXX	IOWR1 [R/W] XXXXXXXX	IOWR2 [R/W] XXXXXXXX		

Address		Plack			
Address	+ 0	+ 1	+ 2	+ 3	Block
0000_067Сн			_		
0000_0680н	CSER [R/W] 00000001	CHER [R/W] XXXXXXX1		TCR [R/W] 00000000*1	Memory IF
0000_0684н	R 00XXXXXX	CR 00XXXXXX			
0000_0688н to 0000_0FFCн			-		Reserved

*1 : An initial value is a different register at the reset level. The display is the one at the INIT level.

*2 : An initial value is a different register at the reset level. The display is due to the INIT level by INITX.

*3 : An initial value is set by the WTH bit of the mode vector.

Address		Register					
Address	+ 0	+ 1	+ 2	+ 3	Block		
0000_1000н							
0000_1004н	XXXX	DMADA0 XXXX XXXXXXXX	[R/W] XXXXXXXX XXX	xxxxx			
0000_1008н	xxxx	_					
0000_100Сн							
0000_1010н	DMASA2 [R/W] XXXXXXXX XXXXXXX XXXXXXXXXXXXXXXXXX				DMAC		
0000_1014н	XXXX	DIVIAC					
0000_1018н	xxxx	DMASA3 XXXX XXXXXXXX	[R/W] XXXXXXXX XXX	xxxxx	_		
0000_101Сн	xxxx	DMADA3 XXXX XXXXXXXX	[R/W] XXXXXXXX XXX	xxxxx	_		
0000_1020н	DMASA4 [R/W] XXXXXXXX XXXXXXX XXXXXXXX XXXXXXXX				_		
0000_1024н	xxxx	DMADA4 XXXX XXXXXXXX	[R/W] XXXXXXXX XXX	xxxxx			
0000_1028н to 0000_FFFCн		-	_		Reserved		

Address		Block			
	+ 0	+1	+ 2	+ 3	BIOCK
010F_0000н	BSR[R] 00000000	BCR[R/W] 00000000	CCR[R/W] 10000000	ADR[R/W] 1XXXXXXX	
010F_0004н	DAR[R/W] XXXXXXXX		—	BC2R[R/W] 00XX0000	I ² C
010F_0008н to 010F_FFFFн		(Rese _	erved) 		

Address		Reg	ister		Block
Address	+ 0	+ 1	+ 2	+ 3	DIOCK
0110_0000н	DLCR0* 0X000000	DLCR1[R, W] 00000000	DLCR2* 00000000		
0110_0004н	DLCR4* 00000010	DLCR5* 01000001	DLCR6* 10000000	DLCR7* 00000000	
0110_0008н	DLCR8[R/W] 00000000	DLCR9[R/W] 00000000	DLCR10[R/W] 00000000	DLCR11[R/W] 00000000	Bank 0
0110_000Сн	DLCR12[R/W] 00000000	DLCR13[R/W] 00000000			
0110_0008н	MAR8[R/W] 00000000	MAR9[R/W] 00000000	MAR10[R/W] 00000000	MAR11[R/W] 00000000	Book 1
0110_000Сн	MAR12[R/W] 00000000	MAR13[R/W] 00000000	MAR14[R/W] 00000000	MAR15[R/W] 00000000	Bank 1
0110_0008н			BMPR10* 00000000	BMPR11* 00000111	
0110_000Сн	BMPR12* 00000000		BMPR14* 00000000		> Bank 2
0110_0010н	BMF 00000000-	-		W] -00000000	
0110_0014н	FILTER_CMD [R/W] XXXXXXXX		-	_	
0110_0018н	FILTER_STATUS [R] XXXXXXXX		-	_	
0110_001Сн	FILTER_DATA [R/W] XXXXXXXX		-	_	
0110_0020н	FL_CONTROL [R/W] XXXXXXXX		-	_	
0110_0024н	FL_SUBNET [R/W] XXXXXXXX		-	_	

MB91401

(Continued)

Address	Register				Block
Address	+ 0	+ 1	+ 2	+ 3	BIOCK
0110_0028н	SMI_CMD[R/W] 00000000-00000000			-	
0110_002Cн	SMI_CMD_ST [R/W] 00XXXXXX				
0110_0030н	SMI_DA ⁻ 00000000-			-	
0110_0034н	SMI_POLLI 00000000-			-	
0110_0038н	SMI_PHY_ADD [R/W] 00000XXX	_		-	
0110_003Cн	SMI_CONTROL [R/W] 111XXXXX			-	
0110_0040н	SMI_STATUS[R] XXXXXXXX			-	SIM IF
0110_0044н	SMI_INTENABLE [R/W] 0XXXXXXX		_		
0110_0048 _H	SMI_MDCDIV [R/W] 01011XXX			-	

* : The attribute is different according to the bit.

Address		Block						
Address	+ 0	+ 1	+ 2	+ 3	Block			
0114_0000н	0	EXIFRXDR [R] 00000000-0000000 0000000-00000000						
0114_0004н	0	EXIFTXDR [W] 00000000-00000000 00000000000000000000						
0114_0008 _H		EXIFRXR[R] — 00000000-00000000 —						
0114_000Cн		EXIFTXR[W] — 00000000000000 —						
0114_0010н		CR[W] 0XXXXXXX		_	 External IF 			
0114_0014н		SR[R] 00XXXXXX		_				
0114_0018н	0	EXIFRXSR 0000000-00000000	[R] 00000000-0000000	0				
0114_001Cн	0	EXIFTXSR [R] 00000000-00000000 00000000000000000000						
0114_0020н	_	_	PIOCR 00000					
0114_0024н	—		PIODR Conne destin	ecting	GPIO			

Address		Block					
Address	+ 0	+ 1	+ 2	+ 3	BIOCK		
0500_03E0н	IR[R/W] 00000000						
0501_0000н to 0501_07FFн		AMR (Attribute Memory Area : window 0)					
0501_1000н to 0501_17FFн		CN (Common Memor	/IR y Area : window 1)				

A 1 1		Disal			
Address —	+ 0	+ 1	+ 2	Block	
0540_0000н	FIFO0 XXXXXXXXX-)0in[W] (-XXXXXXXX	
0540_0004н	FIFO XXXXXXXXX-			D2[W] <-XXXXXXX	
0540_0008H	FIFO3[W] XXXXXXXX-XXXXXXX		-		
0540_000Сн to 0540_001Fн		(Res	erved) —		
0540_0020н		_		Г1[R/W] X-XXX00000	
0540_0024н	CONT2 XXXXXXXX			Г3[R/W] X_XXX00000	
0540_0028н	CONT4 XXXXXXXXX			[5[R/W] (_XXXX00XX	
0540_002Сн	CONT® XXXXXXXXX			[7[R/W] X_XXX00000	USB
0540_0030н	CONT8 XXXXXXXX		CONT9[R/W] XXXXXXXX_0XXX0000		
0540_0034н	CONT1 XXXX0000_				
0540_0038н	TRSIZE 00010001-		-		
0540_003Сн to 0540_003Fн		(Res	erved) 		
0540_0040н	RSIZI XXXXXXXX		-		
0540_0044н	RSIZI XXXXXXXX				
0540_0048н to 0540_005Fн	(Reserved)				
0540_0060н		_		[R/W] 0-00000000	USB
0540_0064н			-		

A ddrooo		Register					
Address	+ 0	+ 1	+ 2	+ 3	- Block		
0540_0068н	ST2 XXXXXXXX		ST3[R/W] XXXXXXX-XXX00000				
0540_006Cн		ST4[R] XXXXX000-00000000		[R/W] X-XX000000			
0540_0070н to 0540_007Вн		(Reserved)					
0540_007Сн	_	_		T[R/W] (-XXXXXX00			
0540_0080н to 0540_FFFFн		(Res	served)				

Addross	Register				Block
Address —	+ 0	+ 1	+ 2	+ 3	BIOCK
0580_0000н	MACRORR[W/R] 00000000-00000001		CARDSR[R/W] 00000000-00000000		
0580_0004н		/R[R/W] -00000000		ISR[R] -00000000	Chip Register
0580_0008н		RP[R/W] -00000000		_	

■ INTERRUPT VECTOR

	Interrup	t number	Interrupt		Address of TBR	
Interrupt source	Decimal	Hexa- decimal	level	Offset	default	RN
Reset	0	00		3FCн	000FFFFCн	
Mode vector	1	01		3F8н	000FFFF8H	_
System reserved	2	02		3F4н	000FFFF4H	_
System reserved	3	03		3F0н	000FFFF0H	
System reserved	4	04		ЗЕСн	000FFFECн	_
System reserved	5	05		3Е8н	000FFFE8н	_
System reserved	6	06		3Е4н	000FFFE4н	
Coprocessor absent trap	7	07		3Е0н	000FFFE0н	_
Coprocessor error trap	8	08		3DCн	000FFFDCн	_
INTE instruction	9	09	_	3D8н	000FFFD8н	
Instruction break exception	10	0A		3D4н	000FFFD4н	_
Operand break trap	11	0B		3D0н	000FFFD0н	
Step trace trap	12	0C	_	3ССн	000FFFCCн	
NMI request (tool)	13	0D		3С8н	000FFFC8н	_
Undefined instruction exception	14	0E		3С4н	000FFFC4н	_
NMI request	15	0F	FH fixed	3С0н	000FFFC0н	
Ethernet MAC IF	16	10	ICR00	3ВСн	000FFFBCн	4
Authentication macro	17	11	ICR01	3В8н	000FFFB8н	5
IPSec Accelerator/Code macro	18	12	ICR02	3В4н	000FFFB4н	8
EX IF/GPIO	19	13	ICR03	3В0н	000FFFB0н	9
USB/I ² C/CARD IF	20	14	ICR04	ЗАСн	000FFFACн	_
External interrupt 5	21	15	ICR05	3А8н	000FFFA8H	
External interrupt 6	22	16	ICR06	3А4н	000FFFA4н	
External interrupt 7	23	17	ICR07	3А0н	000FFFA0н	
Reload timer 0	24	18	ICR08	39Сн	000FFF9Cн	6
Reload timer 1	25	19	ICR09	398н	000FFF98н	7
Reload timer 2	26	1A	ICR10	394н	000FFF94H	_
UART0 (Reception completed)	27	1B	ICR11	390н	000FFF90H	0
UART1 (Reception completed)	28	1C	ICR12	38Cн	000FFF8Cн	1
UART0 (RX completed)	29	1D	ICR13	388н	000FFF88H	2
UART1 (RX completed)	30	1E	ICR14	384 ⊦	000FFF84н	3
DMAC0 (end error) Ethernet MAC IF	31	1F	ICR15	380н	000FFF80н	
DMAC1 (end error) External IF	32	20	ICR16	37Сн	000FFF7Cн	
DMAC2 (end error) USB	33	21	ICR17	378н	000FFF78н	

	Interrup	number	Interrupt		Address of TBR	DN
Interrupt source	Decimal	Hexa- decimal	level	Offset	default	RN
DMAC3 (end, error)	34	22	ICR18	374н	000FFF74н	
DMAC4 (end, error)	35	23	ICR19	370н	000FFF70н	
System reserved	36	24	ICR20	36Сн	000FFF6Cн	_
System reserved	37	25	ICR21	368н	000FFF68н	_
System reserved	38	26	ICR22	364н	000FFF64H	
System reserved	39	27	ICR23	360н	000FFF60н	_
System reserved	40	28	ICR24	35Сн	000FFF5Cн	_
System reserved	41	29	ICR25	358н	000FFF58н	
System reserved	42	2A	ICR26	354н	000FFF54н	_
System reserved	43	2B	ICR27	350н	000FFF50н	_
System reserved	44	2C	ICR28	34Сн	000FFF4Cн	
U-TIMER0	45	2D	ICR29	348н	000FFF48н	
U-TIMER1	46	2E	ICR30	344н	000FFF44H	_
Timebase timer overflow	47	2F	ICR31	340н	000FFF40н	
System reserved	48	30	ICR32	33Сн	000FFF3Cн	_
System reserved	49	31	ICR33	338н	000FFF38н	_
System reserved	50	32	ICR34	334н	000FFF34н	
System reserved	51	33	ICR35	330н	000FFF30н	
System reserved	52	34	ICR36	32Сн	000FFF2Cн	
System reserved	53	35	ICR37	328н	000FFF28н	
System reserved	54	36	ICR38	324н	000FFF24н	
System reserved	55	37	ICR39	320н	000FFF20н	
System reserved	56	38	ICR40	31Сн	000FFF1Cн	
System reserved	57	39	ICR41	318н	000FFF18н	_
System reserved	58	ЗA	ICR42	314н	000FFF14н	
System reserved	59	3B	ICR43	310н	000FFF10н	
System reserved	60	3C	ICR44	30Сн	000FFF0Cн	_
System reserved	61	3D	ICR45	308н	000FFF08н	
System reserved	62	3E	ICR46	304н	000FFF04н	
Delay interrupt source bit	63	3F	ICR47	300н	000FFF00H	
System reserved (Used by REALOS*)	64	40		2FCн	000FFEFCн	
System reserved (Used by REALOS*)	65	41		2F8н	000FFEF8н	
System reserved	66	42		2F4н	000FFEF4н	
System reserved	67	43		2F0н	000FFEF0н	

	Interrup	tnumber	Interrupt		Address of TBR	
Interrupt source	Decimal	Hexa- decimal	level	Offset	default	RN
System reserved	68	44		2ECн	000FFEECн	
System reserved	69	45		2E8н	000FFEE8H	
System reserved	70	46		2E4н	000FFEE4H	
System reserved	71	47		2E0н	000FFEE0H	
System reserved	72	48		2DCн	000FFEDCн	
System reserved	73	49		2D8н	000FFED8н	
System reserved	74	4A		2D4н	000FFED4н	
System reserved	75	4B		2D0н	000FFED0н	
System reserved	76	4C		2CCн	000FFECCн	
System reserved	77	4D		2С8 н	000FFEC8н	
System reserved	78	4E		2C4н	000FFEC4н	
System reserved	79	4F		2С0н	000FFEC0н	
Used by INT instruction	80 to 255	50 to FF		2ВСн to 000н	000FFEBCн to 000FFC00н	

(2) NMI (Non Maskable Interrupt)

NMIs have the highest priority among the interrupt sources handled by this module.

An NMI is always selected whenever other types of interrupt sources occur at the same time.

- If an NMI occurs, the interrupt controller passes the information to the CPU :
- Interrupt level : 15 (01111_B) Interrupt number : 15 (0001111_B)
- NMI detection

NMIs are set and detected by the external interrupt/NMI controller. This module only generates an interrupt level, interrupt number, and MHALTI upon NMI request.

 Suppressing DMA transfer upon NMI request When an NMI request occurs, the MHALTI bit in the HRCL register is set to "1", suppressing DMA transfer. To permit DMA transfer, clear the MHALTI bit to "0" at the end of the NMI routine.

ELECTRICAL CHARACTERISTICS

1. Absolute Maximum Ratings

Parame	tor	Symbol	Ra	ting	Unit	Remarks
Falalie		Symbol	Min	Max	Onic	Remarks
Power supply	I/O	Vdde	VSS - 0.3	VSS + 4.0	V	
voltage*1	Internal	Vddi	VSS - 0.3	VSS + 2.5	V	
Analog power supply	voltage	PLLVDD	VSS - 0.3	VSS + 4.0	V	*2
Input voltage*1		Vı	VSS - 0.3	VDDE + 0.3	V	
Output voltage*1		Vo	VSS - 0.3	VDDE + 0.3	V	
"L" level maximum ou	tput current	lo∟	—	T.B.D	mA	*3
"L" level average outp	"L" level average output current		—	T.B.D	mA	*4
"L" level total maximu	m output current	ΣΙοι	—	T.B.D	mA	
"L" level total average	output cur rent	ΣΙοιαν	—	T.B.D	mA	*5
"H" level maximum ou	Itput current	Іон	—	T.B.D	mA	*3
"H" level average outp	out current	Іонач	—	T.B.D	mA	*4
"H" level total maximu	m output current	ΣІон	—	T.B.D	mA	
"H" level total average	e output cur rent	ΣΙοήαν	—	T.B.D	mA	*5
Power consumption		PD	—	T.B.D	mW	
Operating temperature		Та	- 10	70	°C	
Storage temperature		Tstg	- 55	150	°C	

*1 : This parameter is based on VSS = PLLVSS = 0 V.

*2 : Note that analog power supply voltage and input voltage do not exceed VDDE + 0.3 V at power on.

*3 : The maximum output current is the peak value for a single pin.

*4 : The average output current is the average current for a single pin over a period of 100 ms.

*5 : The total average output current is the average current for all pins over a period of 100 ms.

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

- Notes : Apply equal potential to all of the VDDE pins.
 - Apply equal potential to all of the VDDI pins.
 - Fix all of the VSS pins at 0 V.
 - Leave N.C. pins open.

2. Recommended Operating Conditions

(VSS = PLLVSS = 0 V)

Parameter		Symbol		Unit		
		Symbol	Min	Тур	Max	Onic
Power supply voltage	I/O	Vdde	3.0	3.3	3.6	V
	Internal	Vddi	1.65	1.8	1.95	V
Analog power supply voltage		PLLVDD	VSS + 3.0		VDDE	V
Operating temperature		Та	- 10		70.0	°C

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

3. DC Characteristics

Other than USB

(VSS = PLLVSS = 0 V)

_					Value		
Parameter	Symbol	Pin	Conditions	Min	Тур	Max	Unit
"H" level input voltage	Vн			2.0		VDDE + 0.3	V
"L" level input voltage	Vı∟			VSS - 0.3		0.8	V
"H" level output voltage	Vон		V _{DDE} = 3.0 V, Іон = 4.0 mA	VDDE - 0.5		_	V
"L" level output voltage	Vol		V _{DDE} = 3.0 V, Іон = 4.0 mA	—		0.4	V
Input leak current	lu		Vdde = 3.6 V, Vss < Vi < Vdde	—		± 5	μΑ
Pull-up resistance	Rpulu	TCK/TRST/TMS/ TDI/TDO/ CFCD2X/ CFCD1X/ CFVS1X/CFRDY/ CFWAITX		10	33	80	kΩ
Pull-down resistance	Rpuld	CFRESET		10	33	80	kΩ
Power supply		VDDE	$V_{DDI} = 1.8 V,$	—		T.B.D	mA
current	lcc	VDDI	V _{DDE} = 3.3 V, fc = 50 MHz			T.B.D	mA
Input capacitance	CIN	Without power supply			18		pF

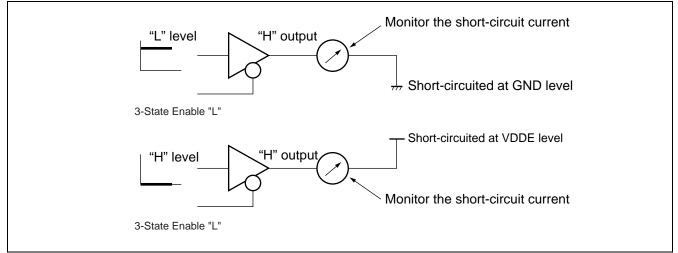
• USB

(VSS =	PLLVSS	= 0 V)
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Parameter	Symbol	mbol Pin Conditions				Unit	Remarks	
Falameter	Symbol	FIII	Conditions	Min	Тур	Max	Unit	Reinarks
"H" level output voltage	Vон	_	Іон = - 100 μА	VDDE-0.2	—	VDDE	V	
"L" level output voltage	Vol		Ιοι = 100 μΑ	0	_	0.2	V	
"H" level output current	Іон		$V_{OH} = V_{DDE} - 0.4 V$	- 20	_	_	mA	
"L" level output current	lo∟		Vol = 0.4 V	20	_	_	mA	
output short circuit current	los				—	300	mA	*1
Input leak current	ILZ					± 5	μA	*2

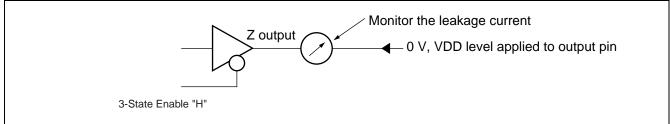
*1: <About the output short-circuit current>

Output short-circuit current los is the maximum current that flows when the output pin is connected to V_DDE or Vss (within the maximum rating). The current is "the short-circuit current per differential output pin." As the USB I/O buffer is a differential output, the short-circuit current should be considered for both of the output pins.



*2: <About Measurement of Z leakage current ILz>

Input leakage current ILZ is measured with the USB I/O buffer in the high-impedance state when the VDDE or Vss voltage is applied to the bidirectional pin.



USB Specification Revision 1.1

	Parameter	Symbol	Va	lue	– Unit	Remarks
	Falameter	Symbol	Min	Max		Remarks
Inp	out Levels		•		·	
	High (driven)	Vih	2.0		V	*1
	Low	Vil		0.8	V	*1
	Diffential Input Sensitivity	Vdi	0.2	—	V	*2
	Differential Common Mode Range	Vсм	0.8	2.5	V	*2
Ou	tput Levels		·		·	
	High (driven)	Vон	0.0	0.3	V	*3
	Low	Vol	2.8	3.6	V	*3
	Output Signal Crossover Voltage	Vcrs	1.3	2.0	V	*4
Те	rminations					
	Bus Pull-up Resistor on Upstream Port	Rpu	1.425	1.575	kΩ	$1.5 \text{ k}\Omega \pm 5\%$
	Termination Voltage for Upstream Port Pull-up	Vterm	3.0	3.6	V	*5

*1 : <Input Levels VIH, VIL>

The switching threshold voltage of the USB I/O buffer's single-end receiver is set within the range from $V_{IL (Max)} = 0.8 V$ to $V_{IH (Min)} = 2.0 V$ (TTL input standard).

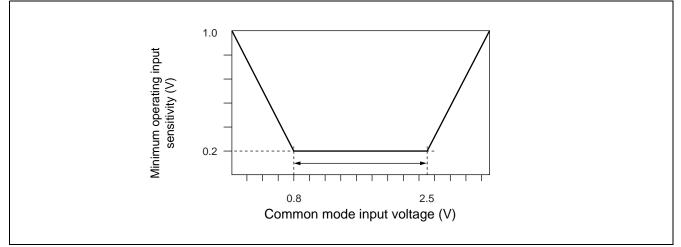
For V_IH and V_IL, the LSI has some hysteresis to reduce noise susceptibility.

*2: <Input Levels VDI, Vсм>

A differential receiver is used to receive USB differential data signals.

The differential receiver has a differential input sensitivity of 200 mV when the differential data input falls within the range from 0.8 V to 2.5 V with respect to the local ground reference level.

The above voltage range is referred to as common-mode input voltage range.

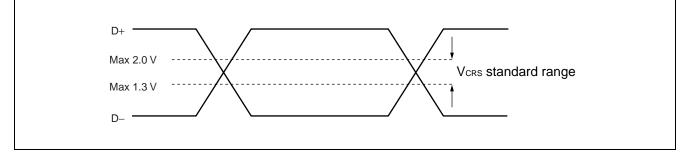


*3: <Output Levels Vol, Voh>

The output driving performance levels of the driver are 0.3 V or less (to 3.6-V, 1.5 k Ω load) in the low state (VoL) and 2.8 V or more (to ground, 1.5 k Ω load) in the high state (VoH).

*4 : <Output Levels Vcrs>

The cross voltage of the external differential output signals (D+ and D–) falls within the range from 1.3 V to 2.0 V.

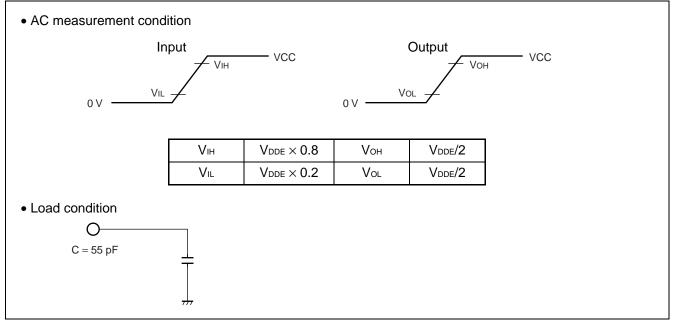


*5 : <Terminations VTERM>

VTERM indicates the pull-up voltage at the upstream port.

4. AC Characteristics

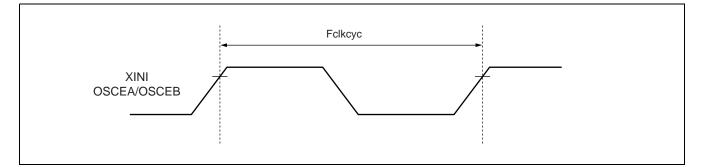
The following measurement conditions depending on the supply voltage apply to the MB91401 unless otherwise specified.



(1) Clock

Parameter	Symbol	Pin	Conditions	Va	lue	Unit	Remarks
Farameter	Symbol	EIII	Conditions	Min	Max	Unit	itemaiks
Input clock frequency	Fclkcyc	XINI	External clock	10.0	50.0	MHz	
	Fclkcyc	OSCEA, OSCEB	Oscillation	10.0	50.0	MHz	
Internal operating clock frequency (FR70E/peripheral module)	Fclkin	_			50.0	MHz	*
Internal operating clock frequency (USBC)	Fusop	_			48.0	MHz	
Internal operating clock frequency (I ² C IF)	Fi2op	_			12.5	MHz	
External memory clock frequency		MCLKO			50.0	MHz	

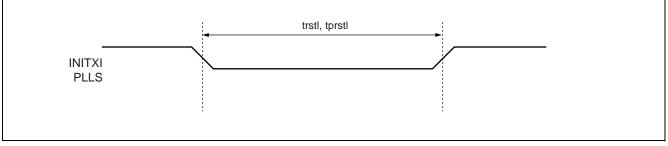
* : The clock frequency must be set to over 25 MHz for the Ethernet MAC interface to perform 100 Base communication.



MB91401

(2) Reset

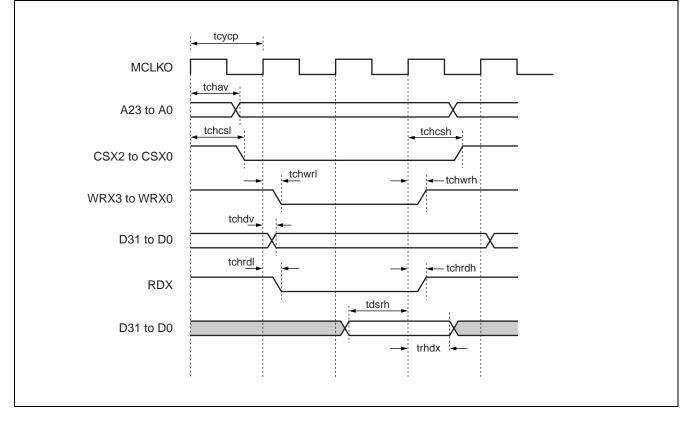
Parameter	Symbol Pin		Cor	ditions	Value		Unit	Remarks		
	Symbol	ГШ	00	lutions	Min	Max	onic	itemai ko		
Posot input time	tretl	trstl INITXI supply &	After power	At unusing of PLL	5 tcp	—	ns			
Reset input time	1150		supply & input clock	At using of PLL	600 + 1	_	μs			
PLL reset input time	tprstl	PLLS	stabilization	At using of PLL	1		μs			
Note : tcp is internal C	Note : tcp is internal CPU and clock cycle period for peripheral module.									



(3) Normal memory access

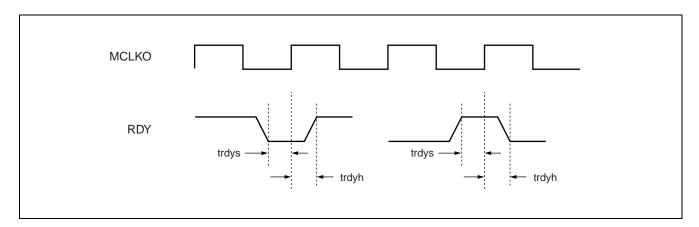
Parameter	Symbol	Pin	Typical timing	Va	lue	Unit	Remarks
Falameter	Symbol	FIII	Typical tinning	Min	Max	Unit	Remarks
Address delay time	tchav	A23 to A0	MCLKO ↑	0	tcycp / 2 + 7	ns	
CSX delay time	tchcsl	CSX2 to CSX0	MCLKO ↑	0	tcycp / 2 + 7	ns	
CSX delay time	tchcsh	CSX2 to CSX0	MCLKO ↑	0	tcycp / 2 + 7	ns	
WRX delay time	tchwrl	WRX3 to WRX0	MCLKO ↑	– 1	9	ns	
WRX delay time	tchwrh	WRX3 to WRX0	MCLKO ↑	- 1	9	ns	
Data delay time	tchdv	D31 to D0	MCLKO ↑	0	tcycp / 2 + 7	ns	
RDX delay time	tchrdl	RDX	MCLKO ↑	– 1	9	ns	
RDX delay time	tchrdh	RDX	MCLKO ↑	- 1	9	ns	
Data setup	tdsrh	D31 to D0	MCLKO ↑	19		ns	
Data hold	trhdx	D31 to D0	MCLKO ↑	- 1		ns	

Note : tcycp is external memory clock cycle period.



(4) Ready input

Parameter	Symbol	Pin	Typical timing	Va	lue	Unit	Remarks
	Symbol	ГШ	Typical tinning	Min	Max	Ome	IVEIIIdi K3
RDY setup	trdys	RDY	MCLKO ↑	19	—	ns	
RDY hold	trdyh	RDY	MCLKO ↑	– 1		ns	



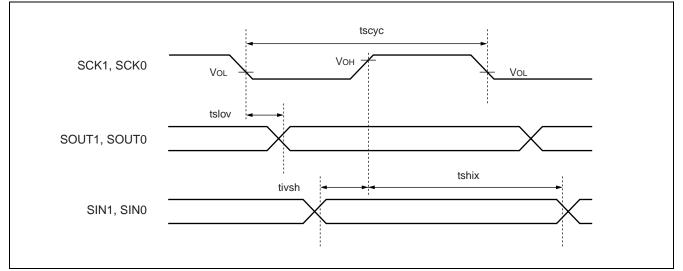
(5) UART

Parameter	Symbol	Pin	Conditions	Val	ue	Unit	Remarks
i arameter	Symbol		Conditions	Min Max		Onit	i temai ka
Serial clock cycle time	tscyc	SCK1, SCK0		8 imes timcycp	—	ns	
$\begin{array}{l} SCLK \downarrow \rightarrow \\ SOUT \text{ delay time} \end{array}$	tslov	SOUT1, SOUT0	Internal shift clock	- 80	80	ns	
Valid SIN → SCLK ↑	tivsh	SIN1, SIN0	mode	100		ns	
$\begin{array}{l} SCLK \uparrow \rightarrow \\ valid \; SIN \; hold \; time \end{array}$	tshix	SIN1, SIN0		60		ns	
Serial clock "H" Pulse Width	tshsl	SCK1, SCK0		4 × timcycp		ns	
Serial clock "L" Pulse Width	tslsh	SCK1, SCK0		4 imes timcycp	—	ns	
$\begin{array}{l} SCLK \downarrow \rightarrow \\ SOUT \text{ delay time} \end{array}$	tslov	SOUT1, SOUT0	External shift clock mode	_	150	ns	
Valid SIN → SCLK ↑	tivsh	SIN1, SIN0		60		ns	
$\begin{array}{l} SCLK \uparrow \rightarrow \\ valid \; SIN \; hold \; time \end{array}$	tshix	SIN1, SIN0		60		ns	

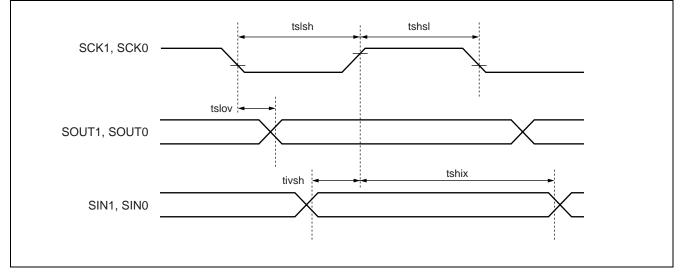
Note : timcycp is operational clock period of peripheral module built-in FR70E core.



• Internal shift clock mode



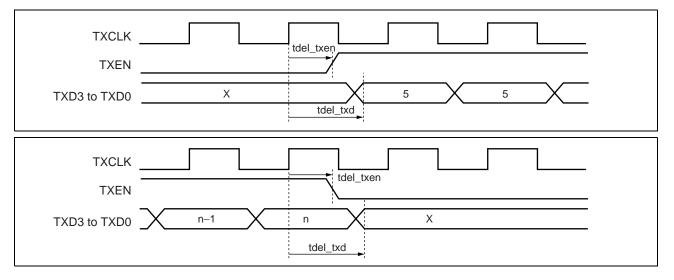
• External shift clock mode



(6) MII interface

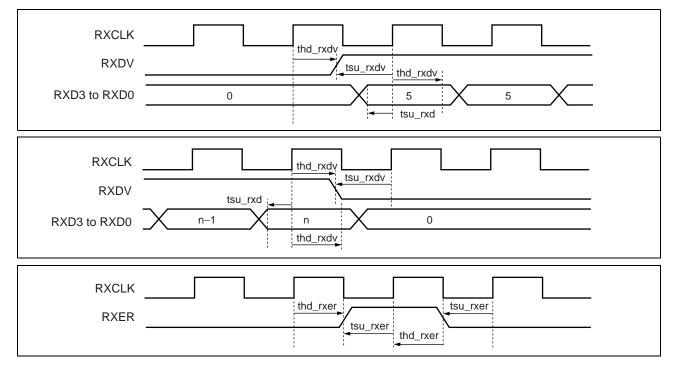
Parameter	Symbol	Pin	Typical timing	Va	lue	Unit	Remarks
Falameter	Symbol	FIII	Typical tilling	Min	Max	Unit	Remarks
TXEN delay time	tdel_txen	TXEN	TXCLK ↑	0	15	ns	
TXD delay time	tdel_txd	TXD3 to TXD0	TXCLK ↑	0	15	ns	
RXDV setup time	tsu_rxdv	RXDV	RXCLK ↑	2	_	ns	
RXSV Hold Time	thd_rxdv	RXDV	RXCLK ↑	3	_	ns	
RXD setup time	tsu_rxd	RXD3 to RXD0	RXCLK ↑	2	_	ns	
RXD Hold Time	thd_rxdv	RXD3 to RXD0	RXCLK ↑	3	_	ns	
RXERsetup time	tsu_rxer	RXER	RXCLK ↑	2		ns	
RXER Hold Time	thd_rxer	RXER	RXCLK ↑	3		ns	

• Transmission



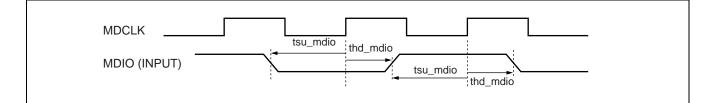
MB91401

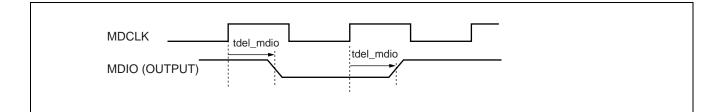
Reception

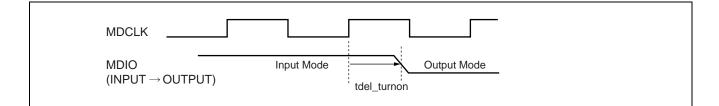


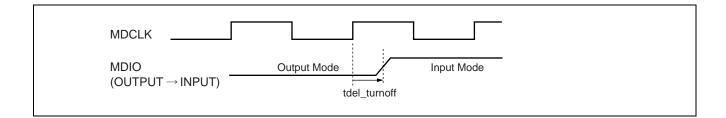
(7) MDIO interface

Parameter	Symbol	Pin	typical timing	Va	lue	Unit	Remarks
Farameter	Symbol	FIII	typical tinning	Min	Max	Unit	Remarks
MDIO setup time	tsu_mdio	MDIO	MDCLK ↑	10		ns	
MDIO Hold Time	thd_mdio	MDIO	MDCLK ↑	0	_	ns	
MDIO delay time	tdel_mdio	MDIO	MDCLK ↑	10	30	ns	
$\begin{array}{l} \text{MDIO switching time} \\ (\text{IN } \rightarrow \text{OUT}) \end{array}$	tdel_turnon	MDIO	MDCLK ↑	10	30	ns	
$\begin{array}{l} \text{MDIO switching time} \\ (\text{OUT} \rightarrow \text{IN}) \end{array}$	tdel_turnoff	MDIO	MDCLK ↑	10	30	ns	







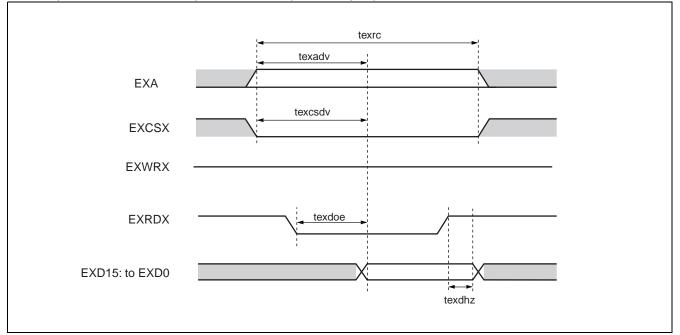


(8) External IF

Read access

Parameter	Symbol	Pin	Va	lue	Unit	Remarks
Falanietei	Symbol	FIII	Min	Max	Onit	itema ko
EX Read Cycle time	texrc	EXA, EXCSX	6 imes tcp	—	ns	
EXA to Data Valid	texadv	EXA, EXD	5 imes tcp	—	ns	
EXCSX to Data Valid	texcsdv	EXCSX, EXD	$5 \times tcp$		ns	
EXRDX to Data Out Enable	texdoe	EXRDX, EXD	5 imes tcp	—	ns	
EXRDX "H" to High Z	texdhz	EXRDX, EXD		$5 \times tcp + 8$	ns	

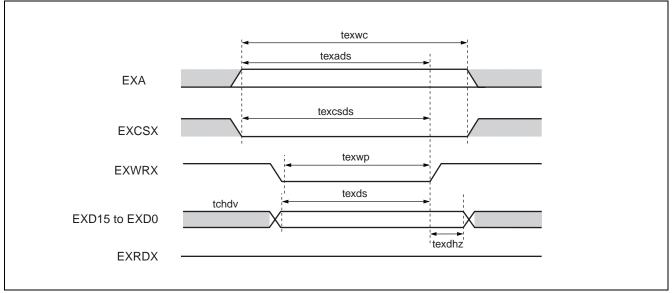
Note : tcp is internal CPU and operational clock period for peripheral module.



Write access

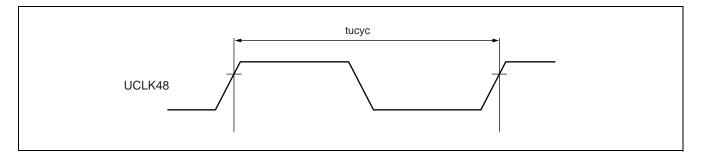
Parameter	Symbol	Pin	Va	lue	Unit	Remarks
Falameter	Symbol	FIII	Min	Max	Unit	Remains
EX Write Cycle time	texwc	EXA, EXCSX	5 imes tcp	_	ns	
EXA to Data Setup time	texads	EXA, EXD	4 imes tcp		ns	
EXCSX to Data Setup time	texcsds	EXCSX, EXD	$4 \times tcp$	_	ns	
EXWRX "L" Pulse width	texwp	EXRDX, EXD	4 imes tcp		ns	
EXD Setup time	texds	EXRDX, EXD	11		ns	
EXD Hold time	texdh	EXRDX, EXD	0	_	ns	

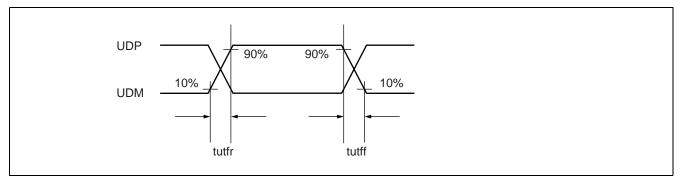
Note : tcp is internal CPU and operational clock period for peripheral module.



(9) USB interface

Parameter	Symbol	Pin		Value		Unit	Remarks
Farameter	Symbol	ГШ	Min	Тур	Max	Unit	Remarks
Input clock	tucyc	UCLK48	—	48* ¹	—	MHz	2500ppm accuracy*1
RISE Time	tutfr	UDP, UDM	4	_	20	ns	*2
Fall Time	tutff	UDP, UDM	4	_	20	ns	*2
Differential Rise and Fall Timing Matching	tutfrfm	UDP, UDM	90		111.11	%	*2
Driver Output Resistance	tzdrv	UDP, UDM	28		44	Ω	*3





*1 : The AC characteristics of the USB interface conform to USB Specification Revision 1.1.

*2 : < Driver Characteristics TFR, TFF, TFRFM>

These items specify the differential data signal rise (trise) and fall (tfall) times.

These are defined as the times between 10% to 90% of the output signal voltage.

For the full-speed buffer, trise and tfall are specified such that the tr/tf ratio falls within \pm 10% to minimize RFI radiation.

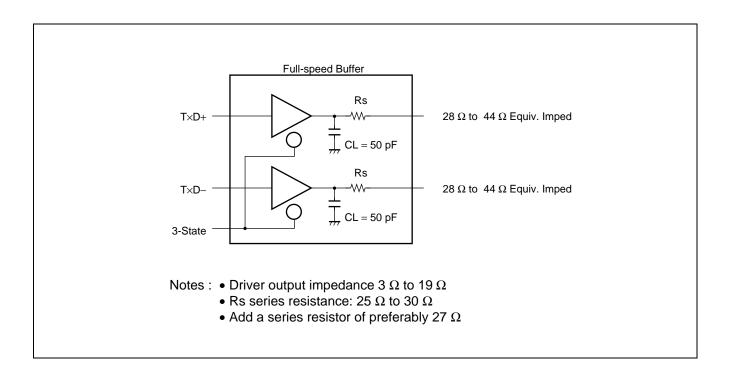
*3 : <Driver Characteristics ZDRV>

USB full-speed connection is performed via a shielded twisted-pair cable at a characteristic impedance of 90 $\Omega\pm15\%$. The USB Standard stipulates that the USB driver's output impedance must be within the range of 28 Ω to 44 Ω . The USB Standard also stipulates that a discrete serial resistor (Rs) must be added to have balance while satisfying the above standard.

The output impedance of the USB I/O buffer on this LSI is about 3 Ω to 19 Ω . Serial resistor Rs to be added must be 25 Ω to 30 Ω (27 Ω recommended).

Capacitor CL of 50 pF must be added as well.

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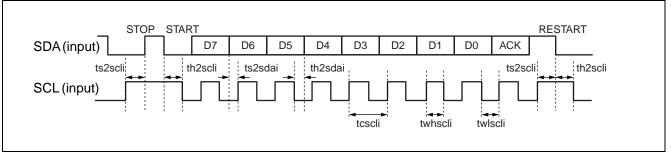


(10) I²C interface

• Input timing specification

Parameter	Symbol	Pin	Va	lue	Unit	Remarks
Farameter	Symbol	FIII	Min	Max	Unit	Remarks
SDA input setup time	ts2sdai	SDA	250		ns	*
SDA input hold time	th2sdai	SDA	0		ns	*
SCL cycle time	tcscli	SCL	10	_	μs	*
SCL input "H" pulse time	twhscli	SCL	4		μs	*
SCL input "L" pulse time	twlscli	SCL	4.7		μs	*
SCL input setup time	ts2scli	SCL	4		μs	*
SCL input hold time	th2scli	SCL	4.7		μs	*

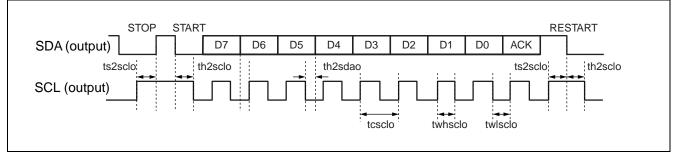
* : Initial Value : I²C bus standards.



• Output timing specification

Parameter	Symbol	Pin	Value		Unit	Remarks
Falailletei	Symbol	FIII	Min	Max	Onit	Remains
SCL output cycle time	tcsclo	SCL	(2×m) +2		PCLK	*
SCL output "H" Pulse Time	twhsclo	SCL	m + 2		PCLK	*
SCL output "L" Pulse Time	twlsclo	SCL	m		PCLK	*
SCL output setup time	ts2sclo	SCL	m + 2		PCLK	*
SCL output hold time	th2sclo	SCL	$m \times 2$		PCLK	*
SDA output hold time	th2sdao	SDA	5		PCLK	*

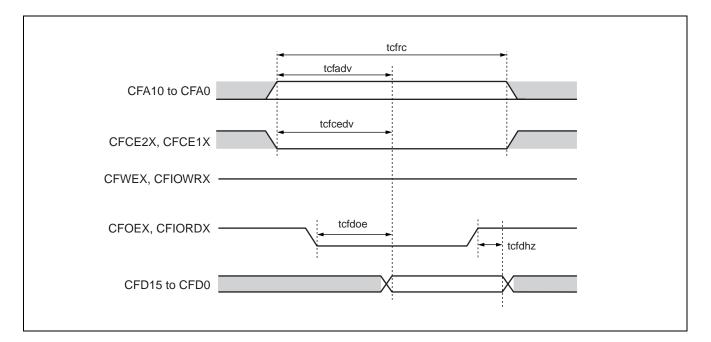
* : For value m, refer to Section 7.5.2.3 "Clock Control Register (CCR) in the I²C Interface Specifications." PCLK indicates I²C interface operating clock frequency.



(11) Card IF

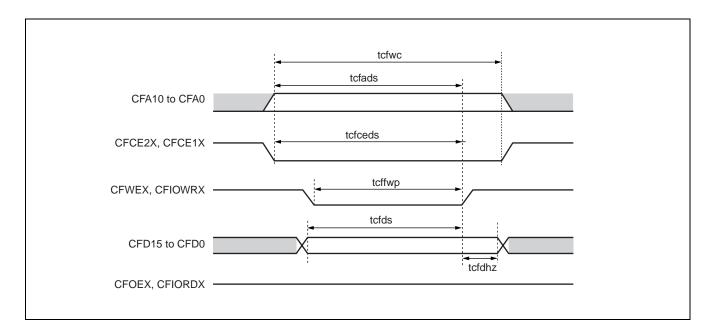
• Read access

Parameter	Symbol Pin –		Va	lue	Unit	Remarks
	Symbol	F 111	Min	Max		itemaiks
CF Read Cycle time	tcfrc	CFA10 to CFA0, CFCE2X, CFCE1X			ns	
CFA to Data Valid	tcfadv	CFA10 to CFA0, CFD15 to CFD0			ns	
CFCEX to Data Valid	tcfcedv	CFCE2X, CFCE1X, CFD15 to CFD0			ns	
CFOEX CFIORDX to Data Out Enable	tcfdoe	CFOEX, CFIORDX, CFD15 to CFD0	—	_	ns	
CFOEX CFIORDX "H" to High Z	tcfdhz	CFOEX, CFIORDX, CFD15 to CFD0			ns	



• Write access

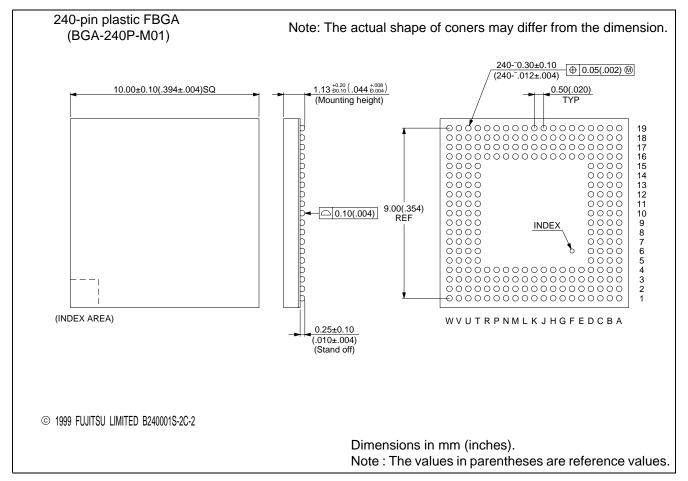
Parameter	Symbol	Pin	Val	ue	Unit	Remarks
Faialletei	Symbol	F 111	Min	Max	Unit	Remarks
CF Write Cycle time	tcfwc	CFA10 to CFA0, CFCE2X, CFCE1X	_	—	ns	
CFA to Data Setup time	tcfads	CFA10 to CFA0, CFD15 to CFD0	_	_	ns	
CFCEX to Data Setup time	tcfceds	CFCE2X, CFCE1X, CFD15 to CFD0			ns	
CFWEX CFIOWRX "L" Pulse width	tcffwp	CFWEX, CFIOWRX	_	_	ns	
CFD Setup time	tcfds	CDWEX, CFIOWRX, CFD15 to CFD0			ns	
CFD Hold time	tcfdhz	CDWEX, CFIOWRX, CFD15 to CFD0			ns	

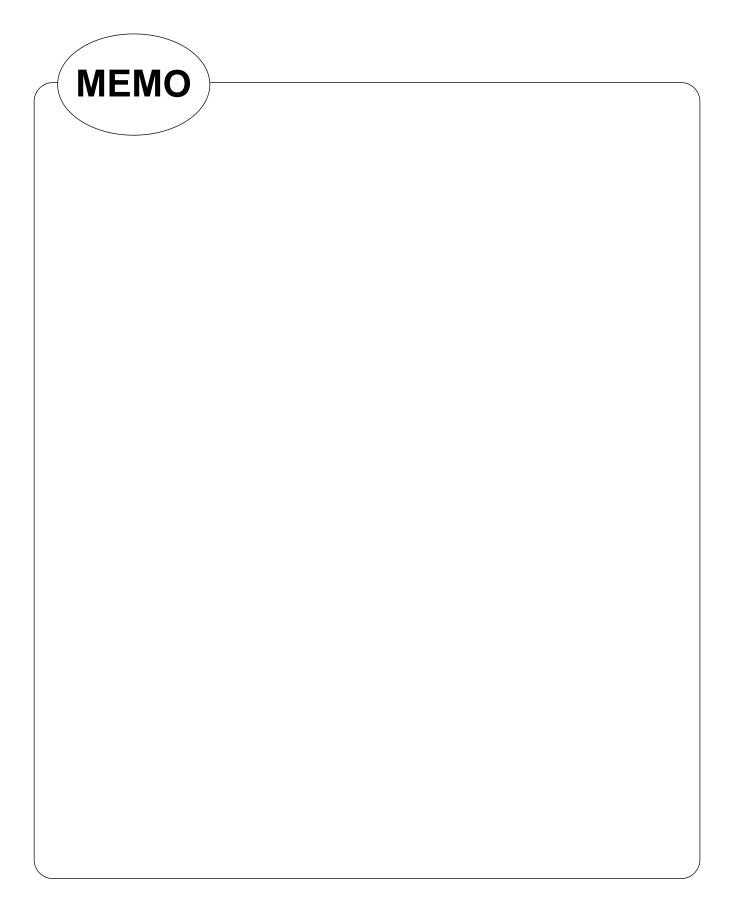


ORDERING INFORMATION

Part number	Package	Remarks
MB91401	240-pin plastic FBGA (BGA-240P-M01)	

PACKAGE DIMENSION





MB91401

FUJITSU LIMITED

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